

# Intel® Desktop Board DB85FL Technical Product Specification

*October 2013*

*Part Number: G89973-003*

The Intel Desktop Board DB85FL may contain design defects or errors known as errata that may cause the product to deviate from published specifications. Current characterized errata are documented in the Intel Desktop Board DB85FL Specification Update.

# Revision History

---

Revision	Revision History	Date
-001	First release of the Intel® Desktop Board DB85FL Technical Product Specification	May 2013
-002	Specification Clarification	July 2013
-003	Specification Clarification	October 2013

This product specification applies to only the standard Intel® Desktop Board with BIOS identifier FLB8510H.86A.

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL® PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER, AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT. UNLESS OTHERWISE AGREED IN WRITING BY INTEL, THE INTEL PRODUCTS ARE NOT DESIGNED NOR INTENDED FOR ANY APPLICATION IN WHICH THE FAILURE OF THE INTEL PRODUCT COULD CREATE A SITUATION WHERE PERSONAL INJURY OR DEATH MAY OCCUR.

All Intel® desktop boards are evaluated as Information Technology Equipment (I.T.E.) for use in personal computers (PC) for installation in homes, offices, schools, computer rooms, and similar locations. The suitability of this product for other PC or embedded non-PC applications or other environments, such as medical, industrial, alarm systems, test equipment, etc. may not be supported without further evaluation by Intel.

Intel Corporation may have patents or pending patent applications, trademarks, copyrights, or other intellectual property rights that relate to the presented subject matter. The furnishing of documents and other materials and information does not provide any license, express or implied, by estoppel or otherwise, to any such patents, trademarks, copyrights, or other intellectual property rights.

Intel may make changes to specifications and product descriptions at any time, without notice.

Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined." Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them.

Intel desktop boards may contain design defects or errors known as errata, which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Contact your local Intel sales office or your distributor to obtain the latest specifications before placing your product order.

Intel and Intel Core are trademarks of Intel Corporation in the U.S. and/or other countries.

\* Other names and brands may be claimed as the property of others.

Copyright © 2013, Intel Corporation. All rights reserved.

# Board Identification Information

## Basic Desktop Board DB85FL Identification Information

AA Revision	BIOS Revision	Notes
G89861	FLB8510H.86A	1,2

Notes:

1. The AA number is found on a small label on the component side of the board.
2. The B85 chipset used on this AA revision consists of the following component:

Device	Stepping	S-Spec Numbers
Intel B85 Express Chipset	C1	SR13C

## Specification Changes or Clarifications

The table below indicates the Specification Changes or Specification Clarifications that apply to the Intel® Desktop Board DH8FL.

### Specification Changes or Clarifications

Date	Type of Change	Description of Changes or Clarifications
July 2013	Spec Clarification	<ul style="list-style-type: none"><li>• Deleted references to ENERGY STAR</li><li>• Deleted the Note in Section 3.9.3 Power Button Menu regarding Fast Boot</li></ul>
October 2013	Spec Clarification	Updated Section 1.3.1.2 to correct the maximum supported resolution for DVI-I

## Errata

Current characterized errata, if any, are documented in a separate Specification Update. See <http://www.intel.com/content/www/us/en/motherboards/desktop-motherboards/motherboards.html?wapkw=desktop+boards> for the latest documentation.

**Intel Desktop Board DB85FL Technical Product Specification**

# Preface

---

This Technical Product Specification (TPS) specifies the board layout, components, connectors, power and environmental requirements, and the BIOS for Intel® Desktop Board DB85FL.

## Intended Audience

The TPS is intended to provide detailed, technical information about Intel Desktop Board DB85FL and its components to the vendors, system integrators, and other engineers and technicians who need this level of information. It is specifically *not* intended for general audiences.

## What This Document Contains

Chapter	Description
1	A description of the hardware used on Intel Desktop Board DB85FL
2	A map of the resources of the Intel Desktop Board
3	The features supported by the BIOS Setup program
4	A description of the BIOS error messages, beep codes, and Power-On Self-Test (POST) codes
5	Regulatory compliance and battery disposal information

## Typographical Conventions

This section contains information about the conventions used in this specification. Not all of these symbols and abbreviations appear in all specifications of this type.

## Notes, Cautions, and Warnings



### NOTE

*Notes call attention to important information.*



### CAUTION

*Cautions are included to help you avoid damaging hardware or losing data.*

## Other Common Notation

#	Used after a signal name to identify an active-low signal (such as USBP0#)
GB	Gigabyte (1,073,741,824 bytes)
GB/s	Gigabytes per second
Gb/s	Gigabits per second
KB	Kilobyte (1024 bytes)
Kb	Kilobit (1024 bits)
kb/s	1000 bits per second
MB	Megabyte (1,048,576 bytes)
MB/s	Megabytes per second
Mb	Megabit (1,048,576 bits)
Mb/s	Megabits per second
TDP	Thermal Design Power
xxh	An address or data value ending with a lowercase h indicates a hexadecimal value.
x.x V	Volts. Voltages are DC unless otherwise specified.
*	This symbol is used to indicate third-party brands and names that are the property of their respective owners.

# Contents

---

## Revision History

Board Identification Information .....	iii
Errata .....	iii

## Preface

Intended Audience.....	v
What This Document Contains.....	v
Typographical Conventions .....	v

## 1 Product Description

1.1 Overview .....	11
1.1.1 Feature Summary .....	11
1.1.2 Board Layout .....	13
1.1.3 Block Diagram .....	15
1.2 Online Support .....	16
1.3 Processor .....	16
1.3.1 Processor Graphics Subsystem.....	17
1.4 System Memory .....	20
1.4.1 Memory Configurations .....	21
1.5 Intel® B85 Express Chipset .....	23
1.5.1 Direct Media Interface (DMI) .....	23
1.5.2 USB.....	23
1.5.3 SATA Interfaces .....	24
1.6 Real-Time Clock Subsystem .....	24
1.7 Super I/O Controller .....	25
1.8 Audio Subsystem.....	25
1.8.1 Audio Subsystem Software .....	25
1.8.2 Audio Subsystem Components .....	26
1.9 LAN Subsystem .....	27
1.9.1 Intel® I217V Gigabit Ethernet Controller.....	27
1.9.2 LAN Subsystem Software .....	28
1.9.3 RJ-45 LAN Connector with Integrated LEDs .....	28
1.10 Hardware Management Subsystem .....	29
1.10.1 Hardware Monitoring .....	29
1.10.2 Fan Monitoring .....	29
1.10.3 Chassis Intrusion and Detection .....	29
1.10.4 Thermal Monitoring .....	30
1.11 Intel® Security and Manageability Technologies .....	31
1.11.5 Intel® Management Engine (Intel® ME) Software and Drivers.....	32
1.12 Power Management .....	33
1.12.1 Software Support (ACPI).....	33
1.12.2 Hardware Support .....	35

## 2 Technical Reference

2.1	Memory Resources .....	39
2.1.1	Addressable Memory.....	39
2.2	Connectors and Headers.....	40
2.2.1	Back Panel Connectors.....	41
2.2.2	Component-side Connectors and Headers.....	42
2.3	BIOS Security Jumper .....	51
2.4	Mechanical Considerations .....	53
2.4.1	Form Factor.....	53
2.5	Electrical Considerations.....	54
2.5.1	Power Supply Considerations .....	54
2.5.2	Fan Header Current Capability .....	55
2.5.3	Add-in Board Considerations.....	55
2.6	Thermal Considerations.....	55
2.7	Reliability .....	58
2.8	Environmental.....	58

## 3 Overview of BIOS Features

3.1	Introduction.....	59
3.2	BIOS Flash Memory Organization.....	60
3.3	Resource Configuration .....	61
3.3.1	PCI Express Autoconfiguration .....	61
3.4	System Management BIOS (SMBIOS) .....	61
3.5	Legacy USB Support .....	61
3.6	BIOS Updates .....	62
3.6.1	Language Support.....	62
3.6.2	Custom Splash Screen .....	63
3.7	BIOS Recovery .....	63
3.8	Boot Options.....	64
3.8.1	Optical Drive Boot .....	64
3.8.2	Network Boot.....	64
3.8.3	Booting Without Attached Devices .....	64
3.8.4	Changing the Default Boot Device During POST.....	64
3.9	Adjusting Boot Speed.....	65
3.9.1	Peripheral Selection and Configuration .....	65
3.9.2	BIOS Boot Optimizations .....	65
3.9.3	Power Button Menu .....	66
3.10	Hard Disk Drive Password Security Feature.....	66
3.11	BIOS Security Features .....	67
3.12	BIOS Performance Features .....	68

## 4 BIOS Error Codes and Messages

4.1	BIOS Error Codes .....	69
4.1.1	BIOS Beep Codes .....	69
4.1.2	Front-panel Power LED Blink Codes .....	70
4.2	BIOS Error Messages .....	70



## 5 Regulatory Compliance and Battery Disposal Information

5.1	Regulatory Compliance.....	71
5.1.1	Safety Standards.....	71
5.1.2	European Union Declaration of Conformity Statement.....	72
5.1.3	Product Ecology Statements.....	73
5.1.4	China RoHS.....	74
5.1.5	EMC Regulations.....	75
5.1.6	e-Standby and ErP Compliance.....	77
5.1.7	Regulatory Compliance Marks (Board Level).....	78
5.2	Battery Disposal Information.....	79

## Figures

1.	Major Board Components.....	13
2.	Block Diagram.....	15
3.	Memory Channel and DIMM Configuration.....	22
4.	Back Panel Audio Connectors.....	26
5.	LAN Connector LED Locations.....	28
6.	Thermal Sensors and Fan Headers.....	30
7.	Location of the Enhanced Standby Power LED.....	38
8.	Back Panel Connectors.....	41
9.	Component-side Connectors and Headers.....	42
10.	Connection Diagram for Front Panel Connector.....	48
11.	Connection Diagram for the Front Panel Dual-Port USB 2.0 Connectors ...	50
12.	Connection Diagram for the Front Panel USB 3.0 Connector.....	50
13.	Location of the Jumper.....	51
14.	Board Dimensions.....	53
15.	Localized High Temperature Zones.....	56
16.	Intel Visual BIOS Screen.....	59
17.	Intel Desktop Board DB85FL China RoHS Material Self Declaration Table .	74

## Tables

1.	Feature Summary.....	11
2.	Components Shown in Figure 1.....	14
3.	DVI Port Status Conditions.....	17
4.	HDMI Port Status Conditions.....	18
5.	Supported Memory Configurations.....	20
6.	Audio Jack Support.....	25
7.	LAN Connector LED States.....	29
8.	Effects of Pressing the Power Switch.....	33
9.	Power States and Targeted System Power.....	34
10.	Wake-up Devices and Events.....	34
11.	Component-side Connectors and Headers Shown in Figure 9.....	43
12.	Front Panel Audio Connector for Intel HD Audio.....	44
13.	Front Panel Audio Connector for AC '97 Audio.....	44

## Intel Desktop Board DB85FL Technical Product Specification

14.	Dual-Port Front Panel USB 2.0 Header.....	44
15.	Internal Mono Speaker Header.....	44
16.	Front Panel USB 3.0 Connector.....	45
17.	SATA Connectors.....	45
18.	S/PDIF Header.....	45
19.	Processor, Front, and Rear Chassis (4-Pin) Fan Headers.....	46
20.	Chassis Intrusion Header.....	46
21.	TPM Header.....	46
22.	Processor Core Power Connector.....	47
23.	Main Power Connector.....	47
24.	Front Panel Connector.....	48
25.	States for a One-Color Power LED.....	49
26.	States for a Two-Color Power LED.....	49
27.	Alternate Front Panel Power/Sleep LED Header.....	49
28.	BIOS Setup Security Jumper Settings.....	52
29.	Fan Header Current Capability.....	55
30.	Thermal Considerations for Components.....	57
31.	Environmental Specifications.....	58
32.	Intel Visual BIOS Setup Display Areas.....	60
33.	BIOS Setup Program Function Keys.....	60
34.	AccepDrives/Media Types for BIOS Recovery.....	63
35.	Boot Device Menu Options.....	64
36.	Master Key and User Hard Drive Password Functions.....	66
37.	Supervisor and User Password Functions.....	68
38.	BIOS Beep Codes.....	69
39.	Front-panel Power LED Blink Codes.....	70
40.	BIOS Error Messages.....	70
41.	Safety Standards.....	71
42.	EMC Regulations.....	75
43.	Regulatory Compliance Marks.....	78

# 1 Product Description

---

## 1.1 Overview

### 1.1.1 Feature Summary

Table 1 summarizes the major features of the board.

**Table 1. Feature Summary**

<b>Form Factor</b>	MicroATX (9.60 inches by 9.60 inches [243.84 millimeters by 243.84 millimeters])
<b>Processor</b>	<ul style="list-style-type: none"><li>• 4<sup>th</sup> generation Intel® Core™ processor with up to 95 W TDP in an LGA1150 socket<ul style="list-style-type: none"><li>– One PCI Express* x16 graphics interface</li><li>– Integrated memory controller with dual channel DDR3 memory support</li><li>– Integrated graphics processing</li><li>– External graphics interface controller</li></ul></li></ul>
<b>Graphics</b>	<ul style="list-style-type: none"><li>• Integrated graphics support for processors with Intel HD Graphics:<ul style="list-style-type: none"><li>– High Definition Multimedia Interface* (HDMI*) v1.4a</li><li>– DVI-I v1.0</li></ul></li><li>• Support for a PCI Express 3.0 x16 add-in graphics card</li></ul>
<b>Memory</b>	<ul style="list-style-type: none"><li>• Four 240-pin DDR3 SDRAM Dual Inline Memory Module (DIMM) sockets</li><li>• Support for DDR3 1333 MHz to DDR3 1600 MHz DIMMs</li><li>• Support for 1 Gb, 2 Gb, and 4 Gb memory technology</li><li>• Support for up to 32 GB of system memory with four DIMMs using 4 Gb memory technology</li><li>• Support for non-ECC memory</li><li>• Support for 1.5 V (standard voltage) and 1.35 V (low voltage) JEDEC memory</li><li>• Support for XMP memory</li></ul>
<b>Chipset</b>	Intel® B85 Express Chipset consisting of the Intel® B85 Express Platform Controller Hub (PCH)

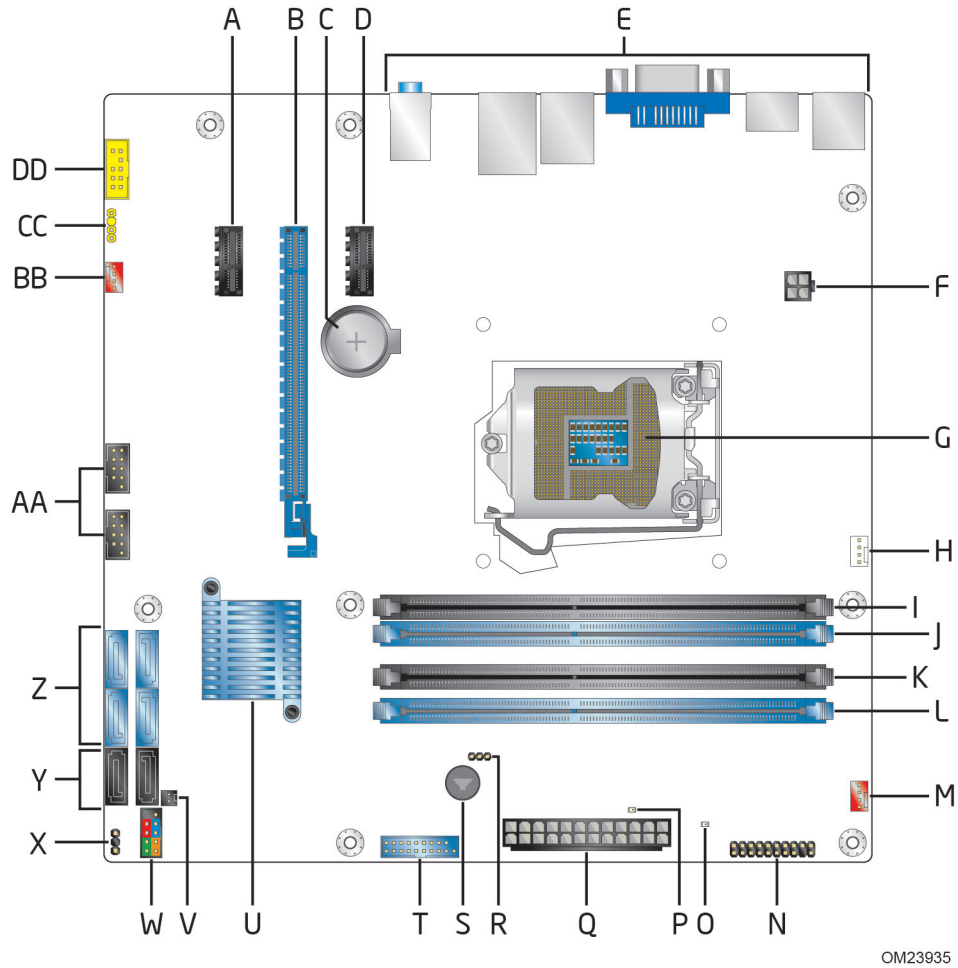
continued

**Table 1. Feature Summary** (continued)

<b>Peripheral Interfaces</b>	<ul style="list-style-type: none"> <li>• USB 3.0 ports:             <ul style="list-style-type: none"> <li>– Two USB 3.0 ports are implemented with stacked back panel connectors</li> <li>– Two front panel USB 3.0 ports are implemented through one internal connector</li> </ul> </li> <li>• USB 2.0 ports:             <ul style="list-style-type: none"> <li>– Four ports are implemented with stacked back panel connectors</li> <li>– Four front panel ports are implemented through two dual-port internal connectors</li> </ul> </li> <li>• Serial ATA (SATA) ports:             <ul style="list-style-type: none"> <li>– Four SATA 6.0 Gb/s ports</li> <li>– Two SATA 3.0 Gb/s ports</li> </ul> </li> </ul>
<b>Audio</b>	8-channel (5.1 + 2) Intel High Definition Audio via the Realtek* ALC662s-VD audio codec
<b>LAN Support</b>	Gigabit (10/100/1000 Mb/s) LAN subsystem using the Intel® I217V Gigabit Ethernet Controller
<b>Expansion Capabilities</b>	<ul style="list-style-type: none"> <li>• One PCI Express x16 3.0/2.x/1.x add-in card connector</li> <li>• Two PCI Express x1 2.x/1.x add-in card connectors</li> </ul>
<b>Intel® Visual BIOS</b>	<ul style="list-style-type: none"> <li>• Intel® BIOS resident in SPI Flash device</li> <li>• Support for Advanced Configuration and Power Interface (ACPI), Plug and Play, and SMBIOS</li> </ul>
<b>Instantly Available PC Technology</b>	<ul style="list-style-type: none"> <li>• Support for PCI Express* Revision 3.0</li> <li>• Suspend to RAM support</li> <li>• Wake on PCI Express, LAN, front panel, and USB ports</li> </ul>
<b>Super I/O Control</b>	Nuvoton NCT6683 I/O controller for hardware management support
<b>Hardware Monitor Subsystem</b>	<ul style="list-style-type: none"> <li>• Hardware monitoring through the Nuvoton I/O controller</li> <li>• Voltage sense to detect out of range power supply voltages</li> <li>• Thermal sense to detect out of range thermal values</li> <li>• Three fan headers</li> <li>• Three fan sense inputs used to monitor fan activity</li> <li>• Fan speed control</li> </ul>
<b>Intel® Security and Manageability Technologies</b>	<ul style="list-style-type: none"> <li>• Intel® Small Business Technology (Intel® SBT)</li> <li>• Intel® Anti-Theft (Intel® AT)</li> <li>• Intel® Virtualization Technology (Intel® VT)</li> <li>• Intel® Virtualization for Directed I/O (Intel® VT-d)</li> </ul>

## 1.1.2 Board Layout

Figure 1 shows the location of the major components on Intel Desktop Board DB85FL.



**Figure 1. Major Board Components**

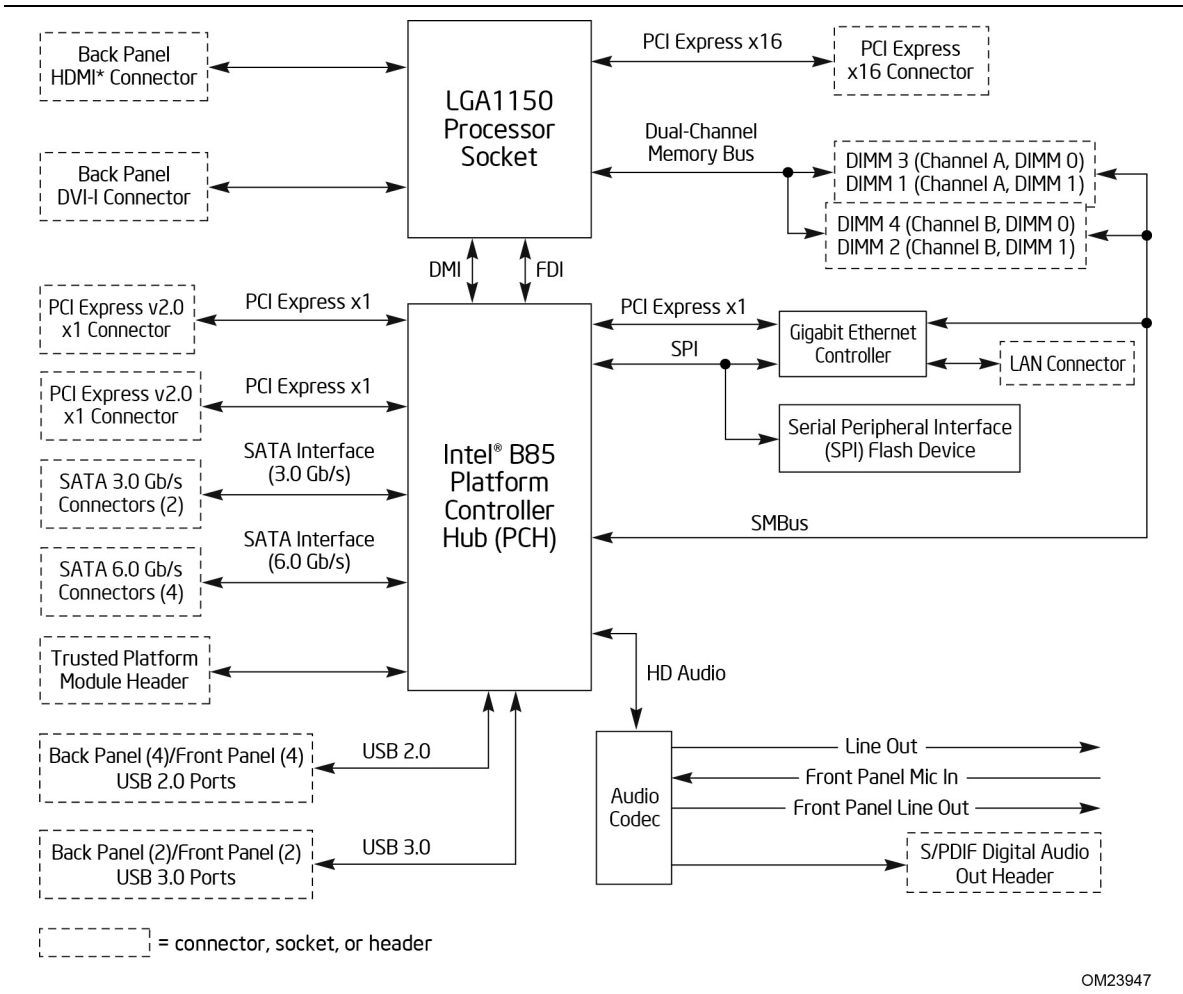
Table 2 lists the components identified in Figure 1.

**Table 2. Components Shown in Figure 1**

<b>Item/callout from Figure 1</b>	<b>Description</b>
A	PCI Express x1 add-in card connector
B	PCI Express x16 add-in card connector
C	Battery
D	PCI Express x1 add-in card connector
E	Back panel connectors
F	Processor core power connector (2 x 2)
G	LGA1150 processor socket
H	Processor fan header
I	DIMM 3 (Channel A DIMM 0)
J	DIMM 1 (Channel A DIMM 1)
K	DIMM 4 (Channel B DIMM 0)
L	DIMM 2 (Channel B DIMM 1)
M	Front fan header
N	Trusted Platform Module header
O	Power supervisor LED
P	Enhanced standby power LED
Q	Main power connector (2 x 12)
R	BIOS security jumper
S	Piezoelectric speaker
T	Front panel USB 3.0 connector
U	Intel B85 Express Chipset
V	Chassis intrusion header
W	Front panel header
X	Alternate front panel power/sleep LED header
Y	SATA 3.0 Gb/s connectors
Z	SATA 6.0 Gb/s connectors
AA	Front panel dual-port USB 2.0 connectors
BB	Rear chassis fan header
CC	S/PDIF out header
DD	Front panel audio connector

### 1.1.3 Block Diagram

Figure 2 is a block diagram of the major functional areas of the board.



**Figure 2. Block Diagram**

## 1.2 Online Support

### To find information about...

Intel Desktop Board DB85FL  
Desktop Board Support  
Available configurations for Intel Desktop Board DB85FL  
Supported processors  
Chipset information  
  
BIOS and driver updates  
Tested memory  
  
Integration information

### Visit this World Wide Web site:

<http://www.intel.com/products/motherboard/index.htm>  
[http://www.intel.com/p/en\\_US/support?iid=hdr+support](http://www.intel.com/p/en_US/support?iid=hdr+support)  
<http://ark.intel.com>  
  
<http://processormatch.intel.com>  
<https://www-ssl.intel.com/content/www/us/en/chipsets/performance-chipsets/chipsets.html>  
<http://downloadcenter.intel.com>  
<http://www.intel.com/support/motherboards/desktop/sb/CS-025414.htm>  
<http://www.intel.com/support/go/buildit>

## 1.3 Processor

The board supports 4<sup>th</sup> generation Intel Core processors. Other processors may be supported in the future. This board supports processors with a maximum wattage of 95 W Thermal Design Power (TDP). The processors listed above are only supported when falling within the wattage requirements of Intel Desktop Board DB85FL. See the Intel web site listed below for the most up-to-date list of supported processors.

### For information about...

### Refer to:

Supported processors

<http://processormatch.intel.com>



### CAUTION

*Use only the processors listed on the web site above. Use of unsupported processors can damage the board, the processor, and the power supply.*



### NOTE

*This board has specific requirements for providing power to the processor. Refer to Section 2.5.1 on page 54 for information on power supply requirements for this board.*



### 1.3.1 Processor Graphics Subsystem

The board supports graphics through either the processor Intel HD Graphics or a PCI Express x16 add-in graphics card.

The board supports integrated graphics for processors with Intel HD Graphics.

#### 1.3.1.1 Intel® High Definition (Intel® HD) Graphics

The Intel HD graphics controller features the following:

- 3D Features
  - DirectX\* 11.1 support
  - OpenGL\* 4.0 support
- Video
  - Next Generation Intel® Clear Video Technology HD support is a collection of video playback and enhancement features that improve the end user's viewing experience
    - Encode/transcode HD content
    - Playback of high definition content including Blu-ray\* disc
    - Superior image quality with sharper, more colorful images
    - Playback of Blu-ray disc S3D content using HDMI (1.4a spec compliant with 3D)
  - DirectX\* Video Acceleration (DXVA) support for accelerating video processing
    - Full AVC/VC1/MPEG2 HW Decode
  - Intel® HD Graphics with Advanced Hardware Video Transcoding (Intel® Quick Sync Video)
    - Note: Intel Quick Sync Video is enabled by an appropriate software application.
  - Blu-ray Stereoscopic 3D (S3D) via HDMI 1.4a

#### 1.3.1.2 Digital Visual Interface (DVI-I)

The DVI-I port supports both digital and analog DVI displays. The maximum supported resolution is 1920 x 1200 @ 60Hz. The DVI port is compliant with the DVI 1.0 specification. DVI analog output can also be converted to VGA using a DVI-VGA converter.

Depending on the type of add-in card installed in the PCI Express x16 connector, the DVI port will behave as described in Table 3.

**Table 3. DVI Port Status Conditions**

PCI Express x16 Connector Status	DVI Digital (DVI-D) Port Status	DVI Analog (DVI-A) Port Status <sup>(Note 1)</sup>
No add-in card installed	Enabled	Enabled
PCI Express x16 add-in card installed	Enabled <sup>(Note 2)</sup>	Enabled <sup>(Note 2)</sup>

Notes:

1. DVI analog output can also be converted to VGA with a DVI-VGA converter.
2. May require BIOS setup menu changes.

### 1.3.1.3 High Definition Multimedia Interface\* (HDMI\*)

The High-Definition Multimedia Interface (HDMI) is provided for transmitting uncompressed digital audio and video signals to television sets, projectors and other video displays. It can carry high quality multi-channel audio data and all standard and high-definition consumer electronics video formats. The HDMI display interface connecting the processor and display devices utilizes transition minimized differential signaling (TMDS) to carry audiovisual information through the same HDMI cable. The processor HDMI interface is designed according to the High-Definition Multimedia Interface Specification with 3D, 4K, Deep Color, and x.v.Color.

The maximum supported resolution is 4096 x 2304 @ 24Hz or 2560 x 1600 @ 60Hz. The HDMI interface supports the HDMI 1.4a specification.

Depending on the type of add-in card installed in the PCI Express x16 connector, the HDMI port will behave as described in Table 4.

**Table 4. HDMI Port Status Conditions**

PCI Express x16 Connector Status	HDMI Port Status
No add-in card installed	Enabled
PCI Express x16 add-in card installed	Enabled <sup>(Note)</sup>

Note: May require BIOS setup menu changes.

### 1.3.1.4 High-bandwidth Digital Content Protection (HDCP)

HDCP is the technology for protecting high definition content against unauthorized copy or interception between a source (computer, digital set top boxes, etc.) and the sink (panels, monitor, and TVs). The PCH supports HDCP 1.4 for content protection over wired displays (HDMI and DVI).

### 1.3.1.5 Integrated Audio Provided by the HDMI Interface

The HDMI interface from the PCH supports audio. The processor supports two High Definition audio streams on two digital ports simultaneously.

The following specific audio technologies are supported by the PCH:

- AC-3 - Dolby\* Digital
- Dolby Digital Plus
- DTS-HD\*
- LPCM, 192 kHz/24 bit, 8 Channel
- Dolby TrueHD, DTS-HD Master Audio\* (Lossless Blu-ray Disc Audio Format)

### 1.3.1.6 Multiple Display Configurations

The following multiple display configuration modes are supported (with appropriate driver software):

- Single Display is a mode with one display port activated to display the output to one display device.
- Intel® Display Clone is a mode with up to three display ports activated to drive the display content of same color depth setting but potentially different refresh rate and resolution settings to all the active display devices connected.
- Extended Desktop is a mode with up to three display ports activated to drive the content with potentially different color depth, refresh rate, and resolution settings on each of the active display devices connected.

### 1.3.1.7 PCI Express Graphics

4<sup>th</sup> generation Intel Core processors support PCI Express 3.0, 2.x, and 1.x:

- PCI Express 3.0 with a raw bit rate of 8.0 GT/s results in an effective bandwidth of 1 GB/s each direction per lane. The maximum theoretical bandwidth of the x16 interface is 16 GB/s in each direction, simultaneously, for a total bandwidth of 32 GB/s.
- PCI Express 2.x with a raw bit rate of 5.0 GT/s results in an effective bandwidth of 500 MB/s each direction per lane. The maximum theoretical bandwidth of the x16 interface is 8 GB/s in each direction, simultaneously, for a total bandwidth of 16 GB/s.
- PCI Express 1.x with a raw bit rate of 2.5 GT/s results in an effective bandwidth of 250 MB/s each direction per lane. The maximum theoretical bandwidth of the x16 interface is 4 GB/s in each direction, simultaneously, for a total bandwidth of 8 GB/s.

---

#### For information about

PCI Express technology

#### Refer to

<http://www.pcisig.com>

---

## 1.4 System Memory

The board has four DIMM sockets and supports the following memory features:

- 1.5 V DDR3 SDRAM DIMMs with gold plated contacts, with the option to raise the voltage to support higher performance DDR3 SDRAM DIMMs.
- 1.35 V Low Voltage DDR3 DIMMs (JEDEC specification)
- Two independent memory channels with interleaved mode support
- Unbuffered, single-sided or double-sided DIMMs with the following restriction: Double-sided DIMMs with x16 organization are not supported.
- 32 GB maximum total system memory (with 4 Gb memory technology). Refer to Section 2.1.1 on page 39 for information on the total amount of addressable memory.
- Minimum recommended total system memory: 1 GB
- Non-ECC DIMMs
- Serial Presence Detect
- DDR3 1333 MHz to DDR3 1600 MHz SDRAM DIMMs
- XMP version 1.3 performance profile support for memory speeds up to 1600 MHz



### NOTE

*To be fully compliant with all applicable DDR SDRAM memory specifications, the board should be populated with DIMMs that support the Serial Presence Detect (SPD) data structure. This allows the BIOS to read the SPD data and program the chipset to accurately configure memory settings for optimum performance. If non-SPD memory is installed, the BIOS will attempt to correctly configure the memory settings, but performance and reliability may be impacted or the DIMMs may not function under the determined frequency.*

Table 5 lists the supported DIMM configurations.

**Table 5. Supported Memory Configurations**

DIMM Capacity	Configuration <sup>(Note)</sup>	SDRAM Density	SDRAM Organization Front-side/Back-side	Number of SDRAM Devices
1024 MB	SS	1 Gbit	128 M x8/empty	8
2048 MB	DS	1 Gbit	128 M x8/128 M x8	16
4096 MB	DS	2 Gbit	256 M x8/256 M x8	16
4096 MB	SS	4 Gbit	512 M x8/empty	8
8192 MB	DS	4 Gbit	512 M x8/512 M x8	16

Note: "DS" refers to double-sided memory modules (containing two rows of SDRAM) and "SS" refers to single-sided memory modules (containing one row of SDRAM).

#### For information about...

Tested Memory

#### Refer to:

<http://support.intel.com/support/motherboards/desktop/sb/CS-025414.htm>

### 1.4.1 Memory Configurations

4<sup>th</sup> generation Intel Core processors support the following types of memory organization:

- **Dual channel (Interleaved) mode.** This mode offers the highest throughput for real world applications. Dual channel mode is enabled when the installed memory capacities of both DIMM channels are equal. Technology and device width can vary from one channel to the other but the installed memory capacity for each channel must be equal. If different speed DIMMs are used between channels, the slowest memory timing will be used.
- **Single channel (Asymmetric) mode.** This mode is equivalent to single channel bandwidth operation for real world applications. This mode is used when only a single DIMM is installed or the memory capacities are unequal. Technology and device width can vary from one channel to the other. If different speed DIMMs are used between channels, the slowest memory timing will be used.
- **Flex mode.** This mode provides the most flexible performance characteristics. The bottommost DRAM memory (the memory that is lowest within the system memory map) is mapped to dual channel operation; the topmost DRAM memory (the memory that is nearest to the 8 GB address space limit), if any, is mapped to single channel operation. Flex mode results in multiple zones of dual and single channel operation across the whole of DRAM memory. To use flex mode, it is necessary to populate both channels.

---

**For information about...**

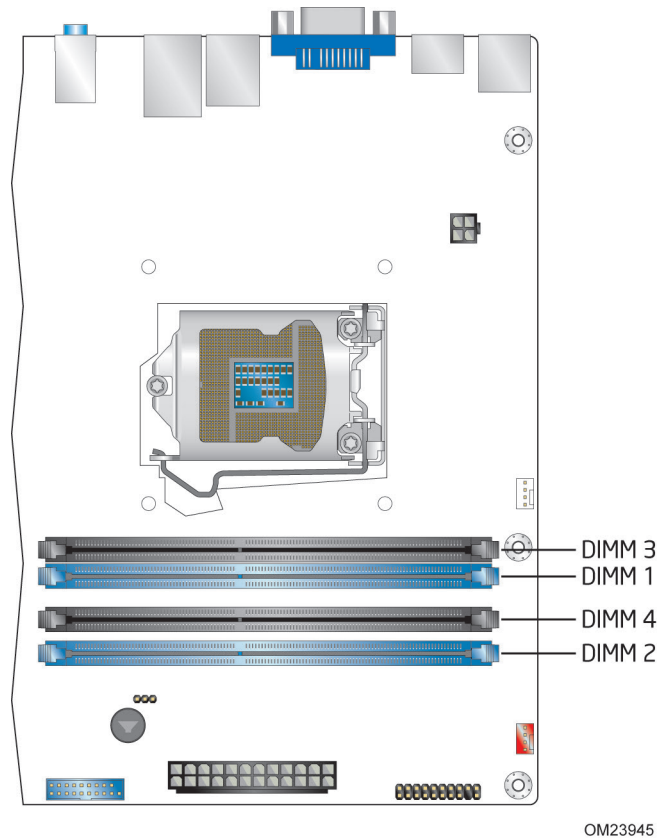
Memory Configuration Examples

**Refer to:**

<http://www.intel.com/support/motherboards/desktop/sb/cs-011965.htm>

---

Figure 3 illustrates the memory channel and DIMM configuration.



**Figure 3. Memory Channel and DIMM Configuration**



**NOTE**

*For best memory performance always install memory in the blue DIMM sockets if installing only two DIMMs on your board.*

## 1.5 Intel® B85 Express Chipset

Intel B85 Express Chipset with Direct Media Interface (DMI) interconnect provides interfaces to the processor and USB, SATA, LPC, LAN, and PCI Express. The Intel B85 Express Chipset is a centralized controller for the board's I/O paths.

For information about	Refer to
The Intel B85 chipset	<a href="http://www.intel.com/products/desktop/chipsets/index.htm">http://www.intel.com/products/desktop/chipsets/index.htm</a>
Resources used by the chipset	Chapter 2

### 1.5.1 Direct Media Interface (DMI)

Direct Media Interface (DMI) is the chip-to-chip connection between the processor and the PCH. This high-speed interface integrates advanced priority-based servicing allowing for concurrent traffic and true isochronous transfer capabilities.

### 1.5.2 USB

The PCH contains up to two Enhanced Host Controller Interface (EHCI) host controllers that support USB high-speed signaling. High-speed USB 2.0 allows data transfers up to 480 Mb/s. All ports are high-speed, full-speed, and low-speed capable.

The PCH also contains an integrated eXtensible Host Controller Interface (xHCI) host controller which supports USB 3.0 ports. This controller allows data transfers up to 5 Gb/s. The controller supports SuperSpeed (SS), high-speed (HS), full-speed (FS), and low-speed (LS) traffic on the bus.

The Intel B85 Express Chipset provides the USB controller for the USB 2.0/3.0 ports. The port arrangement is as follows:

- USB 3.0 ports:
  - Two USB 3.0 ports are implemented with stacked back panel connectors
  - Two front panel USB 3.0 ports are implemented through one internal connector
- USB 2.0 ports:
  - Four ports are implemented with stacked back panel connectors
  - Four front panel ports are implemented through two dual-port internal connectors



#### NOTE

*Computer systems that have an unshielded cable attached to a USB port may not meet FCC Class B requirements, even if no device is attached to the cable. Use a shielded cable that meets the requirements for full-speed devices.*

For information about	Refer to
The location of the USB connectors on the back panel	Figure 8, page 41
The location of the front panel USB headers	Figure 9, page 42

### 1.5.3 SATA Interfaces

The board provides six SATA connectors, through the PCH, which support one device each:

- Four SATA 6.0 Gb/s interfaces through the Intel B85 Express Chipset with SATA ACHI support (blue)
- Two SATA 3.0 Gb/s interfaces through the Intel B85 Express Chipset with SATA ACHI support (black)

The PCH provides independent SATA ports with a theoretical maximum transfer rate of 6.0 Gb/s for four ports and 3.0 Gb/s for two ports. A point-to-point interface is used for host-to-device connections.

The PCH supports the Serial ATA Specification, Revision 3.0. The PCH also supports several optional sections of the Serial ATA II: Extensions to Serial ATA 1.0 Specification, Revision 1.0 (AHCI support is required for some elements).

For more information, see: <http://www.serialata.org/>.

For information about	Refer to
The location of the SATA connectors	Figure 9, page 42

#### 1.5.3.1 Intel® Rapid Storage Technology

The PCH supports Intel® Rapid Storage Technology, providing AHCI functionality.

## 1.6 Real-Time Clock Subsystem

A coin-cell battery (CR2032) powers the real-time clock and CMOS memory. When the computer is not plugged into a wall socket, the battery has an estimated life of three years. When the computer is plugged in, the standby current from the power supply extends the life of the battery. The clock is accurate to  $\pm 13$  minutes/year at 25 °C with 3.3 V<sub>STBY</sub> applied via the power supply 5 V<sub>STBY</sub> rail.



### NOTE

*If the battery and AC power fail, date and time values will be reset and the user will be notified during the Power-On Self-Test (POST).*

When the voltage drops below a certain level, the BIOS Setup program settings stored in CMOS RAM (for example, the date and time) might not be accurate. Replace the battery with an equivalent one. Figure 1 on page 13 shows the location of the battery.



## 1.7 Super I/O Controller

The I/O controller provides the following features:

- Serial IRQ interface compatible with serialized IRQ support for PCI systems
- Intelligent power management, including a programmable wake-up event interface

The BIOS Setup program provides configuration options for the I/O controller.

## 1.8 Audio Subsystem

The board supports Intel HD Audio via the Realtek ALC662s-VD audio codec. The audio subsystem supports the following features:

- Advanced jack sense for the back panel audio jacks that enables the audio codec to recognize the device that is connected to an audio port.
- Digital-to-Analog Converters (DAC) with 95 dB SNR (A-weighting) and Analog-to-Digital Converters (ADC) with 90 dB SNR (A-weighting).
- Six DAC channels support 16/20/24-bit PCM format for 5.1 channel sound playback, plus two channels of concurrent independent stereo sound output (multiple streaming) through the front panel output.
- Two stereo ADCs support 16/20-bit PCM format, multiple stereo recording
- Microphone Acoustic Echo Cancellation (AEC), Noise Suppression (NS), and Beam Forming (BF) technology for voice applications.
- Windows 7 Ultimate and Windows 8 Pro certification.

Table 6 lists the supported functions of the front panel and back panel audio jacks.

**Table 6. Audio Jack Support**

Audio Jack	Micro- phone	Head- phones	Line-out (Front Speakers)	Line-in (Surround)	Mic-in (Center/Sub)
Front panel - Green		Default			
Front panel - Pink	Default				
Back panel - Blue				Default (ctrl panel)	
Back panel - Green		(ctrl panel)	Default (ctrl panel)		
Back panel - Pink					Default (ctrl panel)

### 1.8.1 Audio Subsystem Software

The latest audio software and drivers are available from Intel's World Wide Web site.

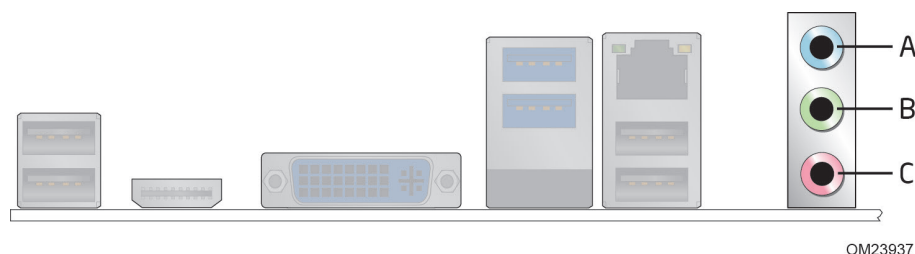
For information about	Refer to
Obtaining audio software and drivers	Section 1.2, page 16

## 1.8.2 Audio Subsystem Components

The audio subsystem includes the following components:

- Intel B85 Express Chipset
- Realtek ALC662s-VD audio codec
- Front panel audio header that supports Intel HD audio and AC '97 audio (a 2 x 5-pin header that provides mic in and line out signals for front panel audio connectors) (yellow)
- S/PDIF digital audio out header (1 x 4-pin header) (yellow)
- 3-port analog audio input/output stack on the back panel
- Mono speaker header (1 x 2-pin header) (yellow)

The back panel audio connectors are configurable through the audio device drivers. The available configurable back panel audio connectors are shown in Figure 4.



OM23937

Item	Description
A	Line-in (Surround)
B	Line-out (Front Speakers)
C	Mic-in (Center/Sub)

**Figure 4. Back Panel Audio Connectors**



### NOTE

*The back panel audio line out connector is designed to power headphones or amplified speakers only. Poor audio quality occurs if passive (non-amplified) speakers are connected to this output.*

For information about	Refer to
The locations of the front panel audio header and S/PDIF audio header	Figure 9, page 42
The signal names of the front panel audio header and S/PDIF audio header	Section 2.2.2.1, page 44
The back panel audio connectors	Section 2.2.1, page 41

### 1.8.2.1 S/PDIF Header

The S/PDIF header allows connections to optical dongles for digital audio output.

### 1.8.2.2 Internal Mono Speaker Header

The internal mono speaker header allows connection to an internal, low-power PC speaker for basic system sound capability. The subsystem is capable of driving a speaker load of 8 Ohms at 1 W (rms) or 4 Ohms at 1.5 W (rms).

## 1.9 LAN Subsystem

The LAN subsystem consists of the following:

- Intel I217V Gigabit Ethernet Controller (10/100/1000 Mb/s)
- Intel B85 Express Chipset
- RJ-45 LAN connector with integrated status LEDs

Additional features of the LAN subsystem include:

- CSMA/CD protocol engine
- LAN connect interface between the PCH and the LAN controller
- ACPI technology support
- LAN wake capabilities
- LAN subsystem software

---

#### For information about

LAN software and drivers

#### Refer to

<http://downloadcenter.intel.com>

---

### 1.9.1 Intel® I217V Gigabit Ethernet Controller

The Intel I217V Gigabit Ethernet Controller supports the following features:

Network Features:

- Compliant with the 1 Gb/s Ethernet 802.3, 802.3u, 802.3z, 802.3ab specifications
- Multi-speed operation: 10/100/1000 Mb/s
- Full-duplex operation at 10/100/1000 Mb/s; Half-duplex operation at 10/100 Mb/s
- Flow control support compliant with the 802.3X specification as well as the specific operation of asymmetrical flow control defined by 802.3z
- VLAN support compliant with the 802.3q specification
- MAC address filters: perfect match unicast filters, multicast hash filtering, broadcast filter, and promiscuous mode

Performance Features:

- Configurable receive and transmit data FIFO, programmable in 1 KB increments
- TCP segmentation capability compatible with Windows NT 5.x off-loading features
- Fragmented UDP checksum offload for packet reassembly
- IPv4 and IPv6 checksum offload support (receive, transmit, and TCP segmentation offload)
- Split header support to eliminate payload copy from user space to host space
- Receive Side Scaling (RSS) with two hardware receive queues
- Supports 9018 bytes of jumbo packets
- Packet buffer size

- LinkSec offload compliant with 802.3ae specification
- TimeSync offload compliant with 802.1as specification

Power Management Features:

- Magic Packet\* wake-up enable with unique MAC address
- ACPI register set and power down functionality supporting D0 and D3 states
- Full wake up support (APM, ACPI)
- MAC power down at Sx, DMOFF with and without WoL
- Auto connect battery saver at S0 no link and Sx no link
- Energy Efficient Ethernet (EEE) support
- Latency Tolerance Reporting (LTR)
- Optimized Buffer Flash/Fill (OBFF) support
- ARP and ND proxy support through LAN Connected Device proxy
- Wake on LAN (WoL) from Deep Sx
- Provides lower power usage to meet ENERGY STAR 5.2 and ErP specifications

### 1.9.2 LAN Subsystem Software

LAN software and drivers are available from Intel’s World Wide Web site.

**For information about**

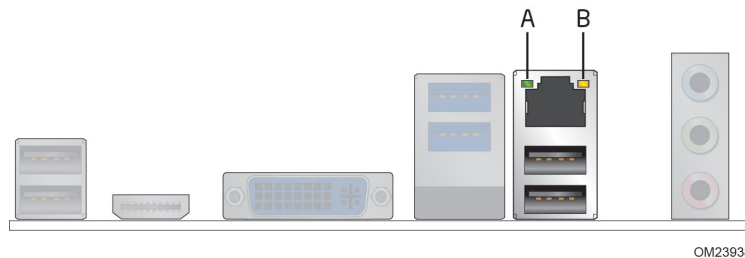
Obtaining LAN software and drivers

**Refer to**

<http://downloadcenter.intel.com>

### 1.9.3 RJ-45 LAN Connector with Integrated LEDs

Two LEDs are built into the RJ-45 LAN connector (shown in Figure 5).



Item	Description
A	Link LED (Green)
B	Data Rate LED (Green/Yellow)

**Figure 5. LAN Connector LED Locations**

Table 7 describes the LED states when the board is powered up and the LAN subsystem is operating.

**Table 7. LAN Connector LED States**

LED	LED Color	LED State	Condition
Link	Green	Off	LAN link is not established.
		On	LAN link is established.
		Blinking	LAN activity is occurring.
Data Rate	Green/Yellow	Off	10 Mb/s data rate is selected.
		Green	100 Mb/s data rate is selected.
		Yellow	1000 Mb/s data rate is selected.

## 1.10 Hardware Management Subsystem

The hardware management features enable the board to be compatible with the Wired for Management (WfM) specification. The board has several hardware management features, including the following:

- Thermal and voltage monitoring
- Chassis intrusion detection

### 1.10.1 Hardware Monitoring

The hardware monitoring and fan control subsystem is based on the Nuvoton NCT6683 device, which supports the following:

- Processor and system ambient temperature monitoring
- Chassis fan speed monitoring
- Power monitoring of +12 V, +5 V, +3.3 V,  $V_{SM}$ ,  $+V_{CCP}$ , and PCH  $V_{CC}$
- SMBus interface

### 1.10.2 Fan Monitoring

Fan monitoring can be implemented using Intel® Desktop Utilities or third-party software.

---

**For information about**

The functions of the fan headers

**Refer to**

Section 1.12.2.2, page 36

---

### 1.10.3 Chassis Intrusion and Detection

The board supports a chassis security feature that detects if the chassis cover is removed. The security feature uses a mechanical switch on the chassis that attaches to the chassis intrusion header. When the chassis cover is removed, the mechanical switch is in the closed position.

---

**For information about**

The location of the chassis intrusion header

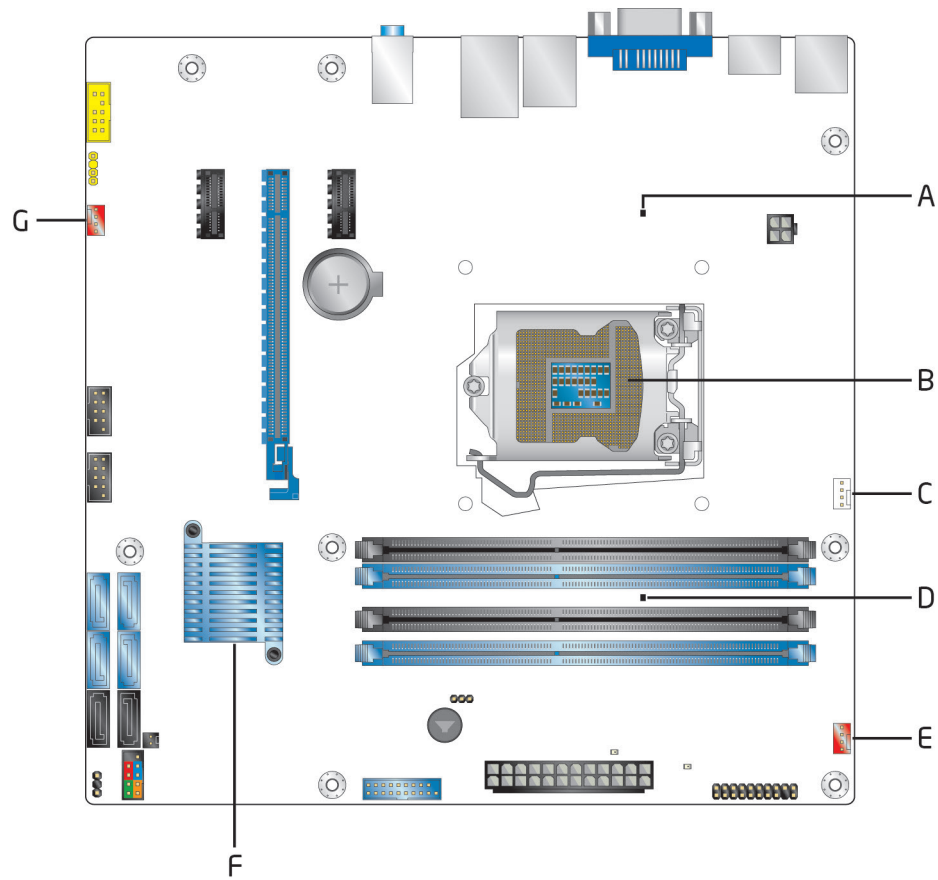
**Refer to**

Figure 9, page 42

---

### 1.10.4 Thermal Monitoring

Figure 6 shows the locations of the thermal sensors and fan headers.



OM23946

Item	Description
A	Voltage regulator thermal sensor
B	Thermal diode, located on the processor die
C	Processor fan header
D	DIMM thermal sensor
E	Front chassis fan header
F	Thermal diode, located on the Intel B85 PCH
G	Rear chassis fan header

**Figure 6. Thermal Sensors and Fan Headers**

## 1.11 Intel® Security and Manageability Technologies

Intel® Security and Manageability Technologies provide tools and resources to help small business owners and IT organizations protect and manage their assets in a business or institutional environment.



### NOTE

*Software with security and/or manageability capability is required to take advantage of Intel platform security and/or management technologies.*

### 1.11.1 Intel® Small Business Technology

Intel® Small Business Technology (Intel® SBT) provides small businesses with security and productivity capabilities to help keep their PCs up-to-date, protected and running well. Intel SBT is the firmware component of Intel® Small Business Advantage (Intel® SBA) and includes this hardware functionality:

- Local Maintenance Timer – Enables applications to “wake-up” the host platform when it is powered down or in a sleep state.
- Local Software Monitor – Provides a common reporting mechanism to monitor applications running on the host operating system.

#### For information about

Intel Small Business Advantage

#### Refer to

<http://www.intel.com/go/SBA>

### 1.11.2 Intel® Virtualization Technology

Intel® Virtualization Technology (Intel® VT) is a hardware-assisted technology that, when combined with software-based virtualization solutions, provides maximum system utilization by consolidating multiple environments into a single server or PC.



### NOTE

*A processor with Intel VT does not guarantee that virtualization will work on your system. Intel VT requires a computer system with a chipset, BIOS, enabling software and/or operating system, device drivers, and applications designed for this feature.*

#### For information about

Intel Virtualization Technology

#### Refer to

<http://www.intel.com/technology/virtualization/technology.htm>

### 1.11.3 Intel® Virtualization Technology for Directed I/O

Intel® Virtualization Technology for Directed I/O (Intel® VT-d) allows addresses in incoming I/O device memory transactions to be remapped to different host addresses. This provides Virtual Machine Monitor (VMM) software with:

- Improved reliability and security through device isolation using hardware assisted remapping.
- Improved I/O performance and availability by direct assignment of devices.

For information about	Refer to
-----------------------	----------

Intel Virtualization Technology for Directed I/O	<a href="http://www.intel.com/technology/itj/2006/v10i3/2-io/4-virtualization-techniques.htm">http://www.intel.com/technology/itj/2006/v10i3/2-io/4-virtualization-techniques.htm</a>
--	---

### 1.11.4 Intel® Anti-Theft Technology

Intel® Anti-Theft (Intel® AT) provides local, tamper-resistant defense that works like a poison pill that disables the computer and access to its data even if the operating system (OS) is reimaged, a new hard drive is installed, or the computer is disconnected from the network.



#### NOTE

*No computer system can provide absolute security under all conditions. Intel AT requires the computer system to have an Intel AT-enabled chipset, BIOS, firmware release, software, and an Intel AT-capable Service Provider/ISV application and service subscription. The detection (triggers), response (actions), and recovery mechanisms only work after the Intel AT functionality has been activated and configured. Certain functionality may not be offered by some ISVs or service providers and may not be available in all countries. Intel assumes no liability for lost or stolen data and/or systems or any other damages resulting thereof.*

For information about	Refer to
-----------------------	----------

Intel Anti-Theft	<a href="http://antitheft.intel.com/welcome.aspx">http://antitheft.intel.com/welcome.aspx</a>
------------------	---

### 1.11.5 Intel® Management Engine (Intel® ME) Software and Drivers

Intel ME software and drivers are available from Intel's World Wide Web site.

For information about	Refer to
-----------------------	----------

Obtaining Intel ME software and drivers	Section 1.2 on page 16
---	------------------------



## 1.12 Power Management

Power management is implemented at several levels, including:

- Software support through Advanced Configuration and Power Interface (ACPI)
- Hardware support

### 1.12.1 Software Support (ACPI)

ACPI gives the operating system direct control over the power management and Plug and Play functions of a computer. The use of ACPI with this board requires an operating system that provides full ACPI support. ACPI features include:

- Plug and Play (including bus and device enumeration)
- Power management control of individual devices, add-in boards (some add-in boards may require an ACPI-aware driver), video displays, and hard disk drives
- Methods for achieving less than 15-watt system operation in the power-on/standby sleeping state
- A Soft-off feature that enables the operating system to power-off the computer
- Support for multiple wake-up events (see Table 10 on page 34)
- Support for a front panel power and sleep mode switch

Table 8 lists the system states based on how long the power switch is pressed, depending on how ACPI is configured with an ACPI-aware operating system.

**Table 8. Effects of Pressing the Power Switch**

<b>If the system is in this state...</b>	<b>...and the power switch is pressed for</b>	<b>...the system enters this state</b>
Off (ACPI G2/G5 – Soft off)	Less than four seconds	Power-on (ACPI G0 – working state)
On (ACPI G0 – working state)	Less than four seconds	Soft-off/Standby (ACPI G1 – sleeping state)
On (ACPI G0 – working state)	More than six seconds	Fail safe power-off (ACPI G2/G5 – Soft off)
Sleep (ACPI G1 – sleeping state)	Less than four seconds	Wake-up (ACPI G0 – working state)
Sleep (ACPI G1 – sleeping state)	More than six seconds	Power-off (ACPI G2/G5 – Soft off)

#### 1.12.1.1 System States and Power States

Under ACPI, the operating system directs all system and device power state transitions. The operating system puts devices in and out of low-power states based on user preferences and knowledge of how devices are being used by applications. Devices that are not being used can be turned off. The operating system uses information from applications and user settings to put the system as a whole into a low-power state.

Table 9 lists the power states supported by the board along with the associated system power targets. See the ACPI specification for a complete description of the various system and power states.

**Table 9. Power States and Targeted System Power**

Global States	Sleeping States	Processor States	Device States	Targeted System Power <sup>(Note 1)</sup>
G0 – working state	S0 – working	C0 – working	D0 – working state.	Full power > 30 W
G1 – sleeping state	S3 – Suspend to RAM. Context saved to RAM.	No power	D3 – no power except for wake-up logic.	Power < 5 W <sup>(Note 2)</sup>
G1 – sleeping state	S4 – Suspend to disk. Context saved to disk.	No power	D3 – no power except for wake-up logic.	Power < 5 W <sup>(Note 2)</sup>
G2/S5	S5 – Soft off. Context not saved. Cold boot is required.	No power	D3 – no power except for wake-up logic.	Power < 5 W <sup>(Note 2)</sup>
G3 – mechanical off AC power is disconnected from the computer.	No power to the system.	No power	D3 – no power for wake-up logic, except when provided by battery or external source.	No power to the system. Service can be performed safely.

Notes:

1. Total system power is dependent on the system configuration, including add-in boards and peripherals powered by the system chassis' power supply.
2. Dependent on the standby power consumption of wake-up devices used in the system.

### 1.12.1.2 Wake-up Devices and Events

Table 10 lists the devices or specific events that can wake the computer from specific states.

**Table 10. Wake-up Devices and Events**

These devices/events can wake up the computer...	...from this state
Power switch	S3, S4, S5 <sup>(Note 1)</sup>
RTC alarm	S3, S4, S5 <sup>(Note 1)</sup>
LAN	S3, S4, S5 <sup>(Notes 1 and 2)</sup>
USB	S3
WAKE#	S3, S4, S5 <sup>(Note 1)</sup>

Notes:

1. S4 implies operating system support only.
2. Wake on LAN is only supported from sleep (S3) or hibernate (S4) in Windows 8.



#### **NOTE**

*The use of these wake-up events from an ACPI state requires an operating system that provides full ACPI support. In addition, software, drivers, and peripherals must fully support ACPI wake events.*

## 1.12.2 Hardware Support



### CAUTION

*Ensure that the power supply provides adequate +5 V standby current if LAN wake capabilities and Instantly Available PC technology features are used. Failure to do so can damage the power supply. The total amount of standby current required depends on the wake devices supported and manufacturing options.*

The board provides several power management hardware features, including:

- Power connector
- Fan headers
- LAN wake capabilities
- Instantly Available PC technology
- Wake from USB
- PCI Express WAKE# signal support
- Wake from S5
- Power Supervisor
- +5 V Standby Power Indicator LED

LAN wake capabilities and Instantly Available PC technology require power from the +5 V standby line.



### NOTE

*The use of Wake from USB from an ACPI state requires an operating system that provides full ACPI support.*

### 1.12.2.1 Power Connector

ATX12V-compliant power supplies can turn off the system power through system control. When an ACPI-enabled system receives the correct command, the power supply removes all non-standby voltages.

When resuming from an AC power failure, the computer returns to the power state it was in before power was interrupted (on or off). The computer's response can be set using the Last Power State feature in the BIOS Setup program's Boot menu.

For information about	Refer to
The location of the main power connector	Figure 9, page 42
The signal names of the main power connector	Table 23, page 47

### 1.12.2.2 Fan Headers

The function/operation of the fan headers is as follows:

- The fans are on when the board is in the S0 state
- The fans are off when the board is off or in the S3, S4, or S5 state
- Each fan header is wired to a fan tachometer input of the SIO
- All fan headers support closed-loop fan control that can adjust the fan speed or switch the fan on or off as needed
- All fan headers have a +12 V DC connection
- The fan headers are controlled by Pulse Width Modulation

For information about	Refer to
The location of the fan headers	Figure 9, page 42
The location of the fan headers and sensors for thermal monitoring	Figure 6, page 30

### 1.12.2.3 LAN Wake Capabilities



#### CAUTION

*For LAN wake capabilities, the +5 V standby line for the power supply must be capable of providing adequate +5 V standby current. Failure to provide adequate standby current when implementing LAN wake capabilities can damage the power supply.*

LAN wake capabilities enable remote wake-up of the computer through a network. The LAN subsystem PCI bus network adapter monitors network traffic at the Media Independent Interface. Upon detecting a Magic Packet\* frame, the LAN subsystem asserts a wake-up signal that powers up the computer. Table 10 on page 34 lists the devices and events that can wake the computer from the S3 state. Depending on the LAN implementation, the board supports LAN wake capabilities with ACPI in the following ways:

- The PCI Express WAKE# signal
- By Ping
- Magic Packet
- The onboard LAN subsystem

### 1.12.2.4 Instantly Available PC Technology



#### CAUTION

*For Instantly Available PC technology, the +5 V standby line for the power supply must be capable of providing adequate +5 V standby current. Failure to provide adequate standby current when implementing Instantly Available PC technology can damage the power supply.*

Instantly Available PC technology enables the board to enter the ACPI S3 (Suspend-to-RAM) sleep-state. While in the S3 sleep-state, the computer will appear to be off (the power supply is off, and the front panel LED is amber if dual colored, or off if single colored.) When signaled by a wake-up device or event, the system quickly returns to

its last known wake state. Table 10 on page 34 lists the devices and events that can wake the computer from the S3 state.

The board supports the *PCI Bus Power Management Interface Specification*. Add-in boards that also support this specification can participate in power management and can be used to wake the computer.

The use of Instantly Available PC technology requires operating system support and PCI Express add-in cards and drivers.

### 1.12.2.5 Wake from USB

USB bus activity wakes the computer from an ACPI S3 state.



#### **NOTE**

*Wake from USB requires the use of a USB peripheral that supports Wake from USB.*

### 1.12.2.6 WAKE# Signal Wake-up Support

When the WAKE# signal on the PCI Express bus is asserted, the computer wakes from an ACPI S3, S4, or S5 state.

### 1.12.2.7 Wake from S5

When the RTC Date and Time is set in the BIOS, the computer will automatically wake from an ACPI S5 state.

### 1.12.2.8 Power Supervisor

The Power Supervisor actively monitors the input voltages from the power supply and protects the board and any attached peripherals from electrical overstress and possible physical damage. The Power Supervisor will activate if it detects the power supply voltage rails have deviated outside the current ATX power supply specification and safe operating levels.

If the Power Supervisor detects an out of spec voltage, the following will happen:

1. The board will be powered down immediately to protect circuits from electrical overstress and possible physical damage.
2. A red warning LED (see Figure 1) on the board will activate as a visual cue.
3. During the next power on, a message will be displayed on the screen to notify the user that the power supply voltage rails have deviated outside the current ATX power supply specification and safe operating levels.
4. A message will be added to the BIOS Event Log for each event that takes place until the BIOS Event Log is cleared.

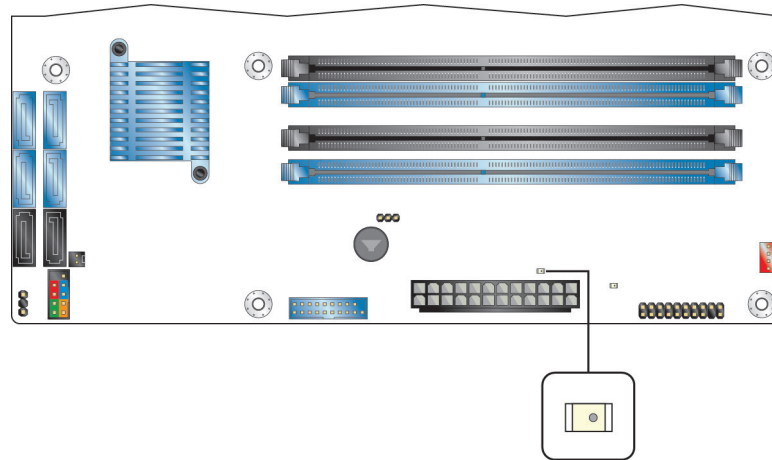
### 1.12.2.9 Enhanced Standby Power LED

The enhanced standby power LED is lit when the board has +5 V standby voltage applied to it. It also blinks as soon as the BIOS has started executing code, once the power button has been pressed and before video has been initialized. Figure 7 shows the location of the LED.



#### CAUTION

*If AC power has been switched off and the standby power indicator is still lit, disconnect the power cord before installing or removing any devices connected to the board. Failure to do so could damage the board and any attached devices.*



OM23943

**Figure 7. Location of the Enhanced Standby Power LED**

## 2 Technical Reference

---

### 2.1 Memory Resources

#### 2.1.1 Addressable Memory

The board utilizes 32 GB of addressable system memory. Typically the address space that is allocated for add-in cards, PCI Express configuration space, BIOS (SPI Flash device), and chipset overhead resides above the top of DRAM (total system memory). On a system that has 32 GB of system memory installed, it is not possible to use all of the installed memory due to system address space being allocated for other system critical functions. These functions include the following:

- BIOS/SPI Flash device (96 Mb)
- Local APIC (19 MB)
- Direct Media Interface (40 MB)
- PCI Express configuration space (256 MB)
- PCH base address registers PCI Express ports (up to 256 MB)
- Memory-mapped I/O that is dynamically allocated for PCI Express add-in cards (256 MB)

The board provides the capability to reclaim the physical memory overlapped by the memory mapped I/O logical address space. The board remaps physical memory from the top of usable DRAM boundary to the 4 GB boundary to an equivalent sized logical address range located just above the 4 GB boundary. All installed system memory can be used when there is no overlap of system addresses.

## 2.2 Connectors and Headers



### CAUTION

*Only the following connectors and headers have overcurrent protection: back panel and front panel USB.*

*The other internal connectors and headers are not overcurrent protected and should connect only to devices inside the computer's chassis, such as fans and internal peripherals. Do not use these connectors or headers to power devices external to the computer's chassis. A fault in the load presented by the external devices could cause damage to the computer, the power cable, and the external devices themselves.*

*Furthermore, improper connection of USB header single wire connectors may eventually overload the overcurrent protection and cause damage to the board.*

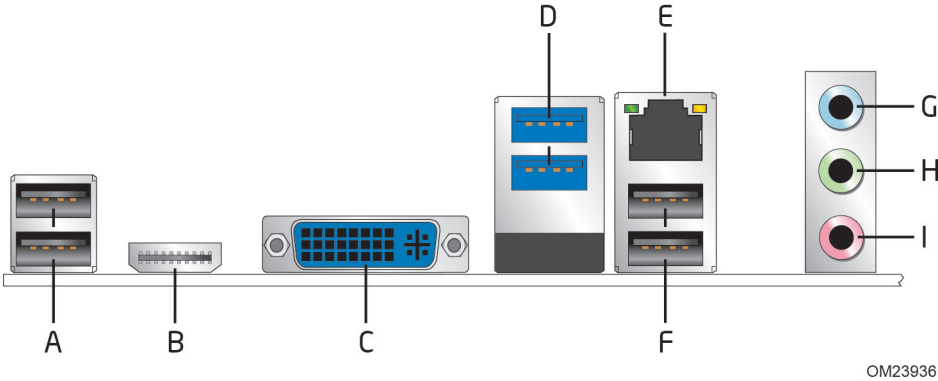
This section describes the board's connectors. The connectors can be divided into these groups:

- Back panel I/O connectors
- Component-side connectors and headers (see page 42)



### 2.2.1 Back Panel Connectors

Figure 8 shows the location of the back panel connectors for the board.



Item	Description
A	USB 2.0 connectors
B	HDMI connector
C	DVI-I connector
D	USB 3.0 connectors
E	LAN port
F	USB 2.0 connectors
G	Line-in (surround)
H	Line-out (front speakers)
I	Mic-in (center/sub)

OM23936

**Figure 8. Back Panel Connectors**

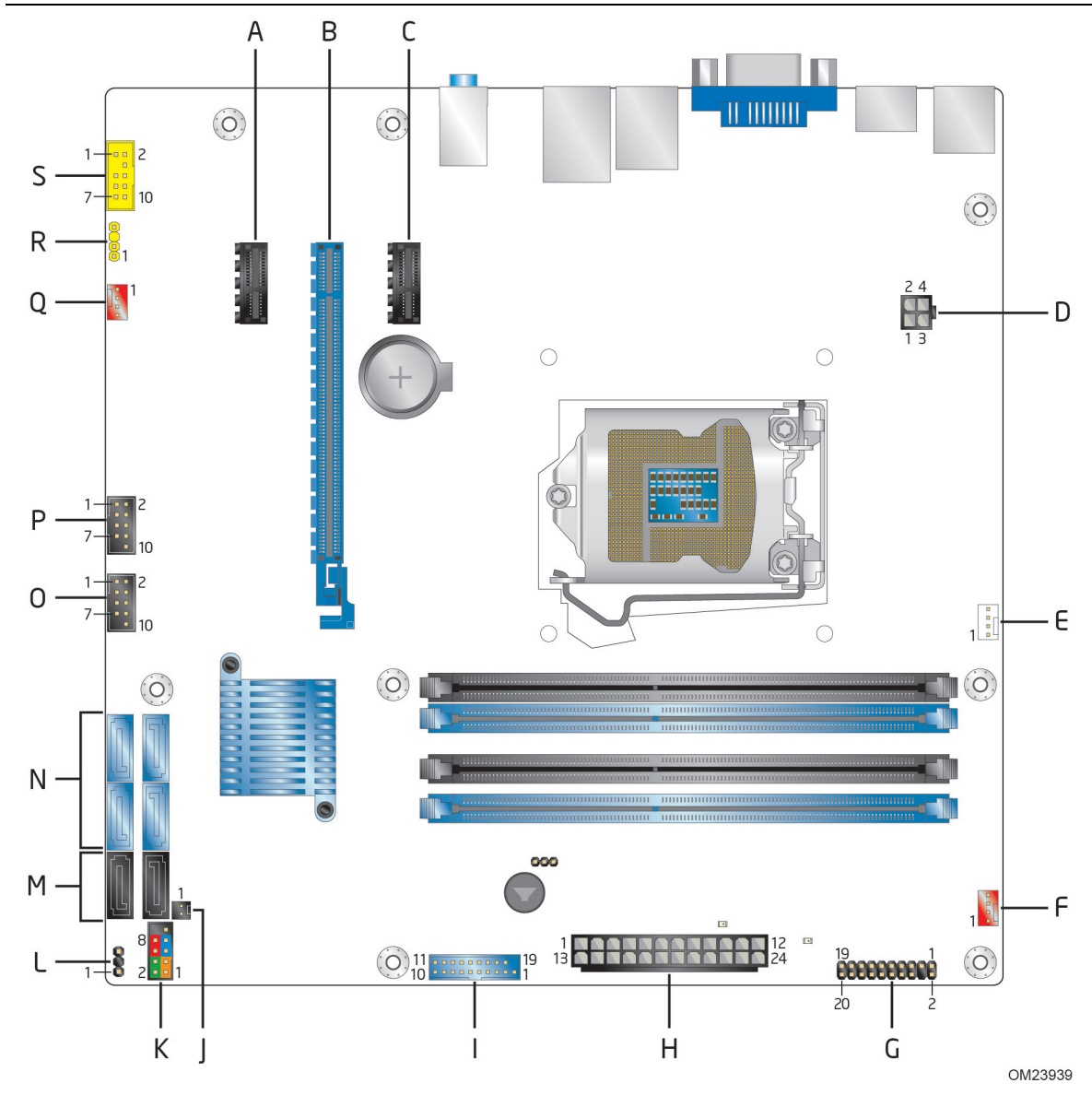


**NOTE**

The back panel audio line out connector is designed to power headphones or amplified speakers only. Poor audio quality occurs if passive (non-amplified) speakers are connected to this output.

## 2.2.2 Component-side Connectors and Headers

Figure 9 shows the locations of the component-side connectors and headers.



OM23939

Figure 9. Component-side Connectors and Headers

Table 11 lists the component-side connectors and headers identified in Figure 9.

**Table 11. Component-side Connectors and Headers Shown in Figure 9**

Item/callout from Figure 9	Description
A	PCI Express x1 add-in card connector
B	PCI Express x16 add-in card connector
C	PCI Express x1 add-in card connector
D	Processor core power connector (2 x 2)
E	Processor fan header
F	Front fan header
G	TPM header
H	Main power connector (2 x 12)
I	Front panel USB 3.0 connector
J	Chassis intrusion header
K	Front panel header
L	Alternate front panel power/sleep LED header
M	SATA 3.0 Gb/s connectors
N	SATA 6.0 Gb/s connectors
O	Front panel dual-port USB 2.0 connector
P	Front panel dual-port USB 2.0 connector
Q	Rear chassis fan header
R	S/PDIF out header
S	Front panel audio connector

### 2.2.2.1 Signal Tables for the Connectors and Headers

**Table 12. Front Panel Audio Connector for Intel HD Audio**

Pin	Signal Name	Pin	Signal Name
1	[Port 1] Left channel	2	Ground
3	[Port 1] Right channel	4	PRESENCE# (Dongle present)
5	[Port 2] Right channel	6	[Port 1] SENSE_RETURN
7	SENSE_SEND (Jack detection)	8	Key (no pin)
9	[Port 2] Left channel	10	[Port 2] SENSE_RETURN

**Table 13. Front Panel Audio Connector for AC '97 Audio**

Pin	Signal Name	Pin	Signal Name
1	MIC	2	AUD_GND
3	MIC_BIAS	4	PRESENCE#
5	[Port 2] Right channel	6	[Port 1] SENSE_RETURN
7	SENSE_SEND (Jack detection)	8	Key (no pin)
9	[Port 2] Left channel	10	[Port 2] SENSE_RETURN

**Table 14. Dual-Port Front Panel USB 2.0 Header**

Pin	Signal Name	Pin	Signal Name
1	+5 V DC	2	+5 V DC
3	D-	4	D-
5	D+	6	D+
7	Ground	8	Ground
9	KEY (no pin)	10	No Connect

Notes: The +5 V DC power on the USB headers is fused.  
The Serial POST pin is reserved for compatibility with future POST debug cards

**Table 15. Internal Mono Speaker Header**

Pin	Signal Name
1	-
2	+

**Table 16. Front Panel USB 3.0 Connector**

Pin	Signal Name	Description
1	Vbus	Power
2	IntA_P1_SSRX-	USB 3 ICC Port1 SuperSpeed Rx-
3	IntA_P1_SSRX+	USB 3 ICC Port1 SuperSpeed Rx+
4	GND	Ground
5	IntA_P1_SSTX-	USB 3 ICC Port1 SuperSpeed Tx-
6	IntA_P1_SSTX+	USB 3 ICC Port1 SuperSpeed Tx+
7	GND	Ground
8	IntA_P1_D-	USB 3 ICC Port1 D- (USB 2 Signal D-)
9	IntA_P1_D+	USB 3 ICC Port1 D+ (USB 2 Signal D+)
10	ID	Over Current Protection
11	IntA_P2_D+	USB 3 ICC Port2 D+ (USB 2 Signal D+)
12	IntA_P2_D-	USB 3 ICC Port2 D- (USB 2 Signal D-)
13	GND	Ground
14	IntA_P2_SSTX+	USB 3 ICC Port2 SuperSpeed Tx+
15	IntA_P2_SSTX-	USB 3 ICC Port2 SuperSpeed Tx-
16	GND	Ground
17	IntA_P2_SSRX+	USB 3 ICC Port2 SuperSpeed Rx+
18	IntA_P2_SSRX-	USB 3 ICC Port2 SuperSpeed Rx-
19	Vbus	Power
20	Key (no pin)	No connect

**Table 17. SATA Connectors**

Pin	Signal Name
1	Ground
2	TXP
3	TXN
4	Ground
5	RXN
6	RXP
7	Ground

**Table 18. S/PDIF Header**

Pin	Signal Name
1	Ground
2	S/PDIF out
3	Key (no pin)
4	+5 V DC

**Table 19. Processor, Front, and Rear Chassis (4-Pin) Fan Headers**

Pin	Signal Name
1	Ground (Note)
2	+12 V
3	FAN_TACH
4	FAN_CONTROL

Note: These fan headers use Pulse Width Modulation control for fan speed.

**Table 20. Chassis Intrusion Header**

Pin	Signal Name
1	Intruder#
2	Ground

**Table 21. TPM Header**

Pin	Signal Name	Pin	Signal Name
1	PCICLK	2	GND
3	FRAME	4	Key (no pin)
5	PCIRST	6	N/C
7	LAD3	8	LAD2
9	VCC3	10	LAD1
11	LAD0	12	GND
13	N/C	14	N/C
15	3VSB	16	SERIRQ
17	GND	18	CLKRUN
19	PWRDWN	20	N/C

### 2.2.2.2 Add-in Card Connectors

The board has the following add-in card connectors:

- One PCI Express x16 (3.0/2.x/1.x)
- Two PCI Express x1 (2.x/1.x)

### 2.2.2.3 Power Supply Connectors

The board has the following power supply connectors:

- **Main power** – a 2 x 12 connector. This connector is compatible with 2 x 10 connectors previously used on Intel Desktop boards. The board supports the use of ATX12V power supplies with either 2 x 10 or 2 x 12 main power cables. When using a power supply with a 2 x 10 main power cable, attach that cable to the main power connector, leaving pins 11, 12, 23, and 24 unconnected.
- **Processor core power** – a 2 x 2 connector. This connector provides power directly to the processor voltage regulator and must always be used. Failure to do so will prevent the board from booting.

**Table 22. Processor Core Power Connector**

Pin	Signal Name	Pin	Signal Name
1	Ground	2	Ground
3	+12 V	4	+12 V

**Table 23. Main Power Connector**

Pin	Signal Name	Pin	Signal Name
1	+3.3 V	13	+3.3 V
2	+3.3 V	14	-12 V
3	Ground	15	Ground
4	+5 V	16	PS-ON# (power supply remote on/off)
5	Ground	17	Ground
6	+5 V	18	Ground
7	Ground	19	Ground
8	PWRGD (Power Good)	20	No connect
9	+5 V (Standby)	21	+5 V
10	+12 V	22	+5 V
11	+12 V (Note)	23	+5 V (Note)
12	2 x 12 connector detect (Note)	24	Ground (Note)

Note: When using a 2 x 10 power supply cable, this pin will be unconnected.

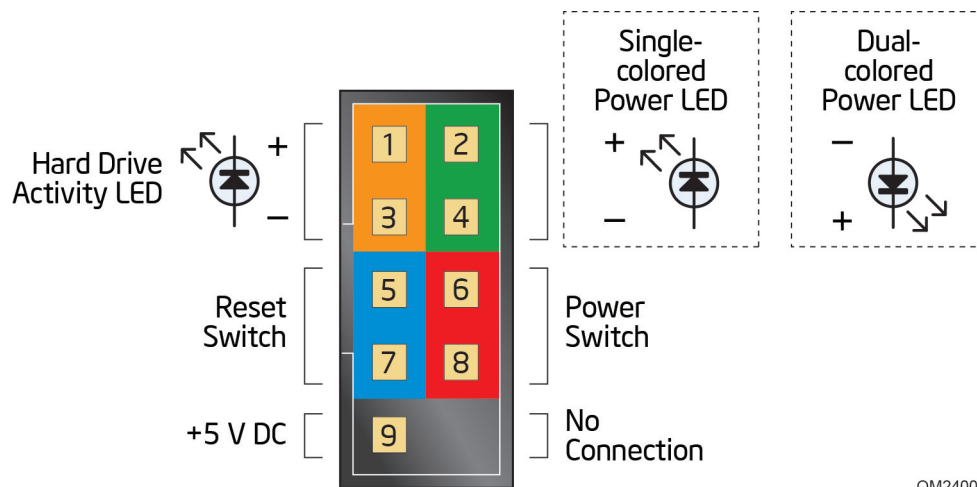
For information about	Refer to
Power supply considerations	Section 2.5.1 on page 54

### 2.2.2.4 Front Panel Connector

This section describes the functions of the front panel connector. Table 24 lists the signal names of the front panel connector. Figure 10 is a connection diagram for the front panel connector.

**Table 24. Front Panel Connector**

Pin	Signal Name	Description	Pin	Signal Name	Description
1	HDD_POWER_LED	Pull-up resistor (750 Ω) to +5 V	2	POWER_LED_MAIN	[Out] Front panel LED (main color)
3	HDD_LED#	[Out] Hard disk activity LED	4	POWER_LED_ALT	[Out] Front panel LED (alt color)
5	GROUND	Ground	6	POWER_SWITCH#	[In] Power switch
7	RESET_SWITCH#	[In] Reset switch	8	GROUND	Ground
9	+5 V_DC	Power	10	Key	No pin



OM24009

**Figure 10. Connection Diagram for Front Panel Connector**

#### 2.2.2.4.1 Hard Drive Activity LED

Pins 1 and 3 can be connected to an LED to provide a visual indicator that data is being read from or written to a hard drive. Proper LED function requires a SATA hard drive or optical drive connected to an onboard SATA connector.

#### 2.2.2.4.2 Reset Switch

Pins 5 and 7 can be connected to a momentary single pole, single throw (SPST) type switch that is normally open. When the switch is closed, the board resets and runs the POST.



### 2.2.2.4.3 Power/Sleep LED

Pins 2 and 4 can be connected to a one- or two-color LED. Table 25 shows the possible states for a one-color LED. Table 26 shows the possible states for a two-color LED.

**Table 25. States for a One-Color Power LED**

LED State	Description
Off	Power off/sleeping
Steady Green	Running

**Table 26. States for a Two-Color Power LED**

LED State	Description
Off	Power off
Steady Green	Running
Steady Yellow	Sleeping



#### NOTE

*The colors listed in Table 25 and Table 26 are suggested colors only. Actual LED colors are chassis-specific.*

### 2.2.2.4.4 Power Switch Header

Pins 6 and 8 can be connected to a front panel momentary-contact power switch. The switch must pull the SW\_ON# pin to ground for at least 50 ms to signal the power supply to switch on or off. (The time requirement is due to internal debounce circuitry on the board.) At least two seconds must pass before the power supply will recognize another on/off signal.

### 2.2.2.5 Alternate Front Panel Power/Sleep LED Header

Pins 1 and 3 of this header duplicate the signals on pins 2 and 4 of the front panel header.

**Table 27. Alternate Front Panel Power/Sleep LED Header**

Pin	Signal Name	Description
1	POWER_LED_MAIN	[Out] Front panel LED (main color)
2	Key (no pin)	
3	POWER_LED_ALT	[Out] Front panel LED (alt color)

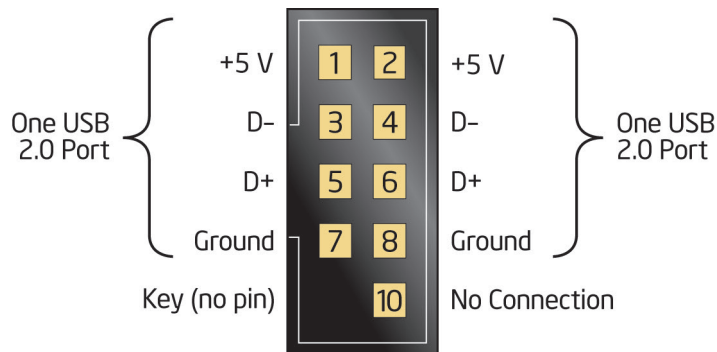
### 2.2.2.6 Front Panel Connectors

Figure 11 and Figure 12 are connection diagrams for the front panel USB connectors.



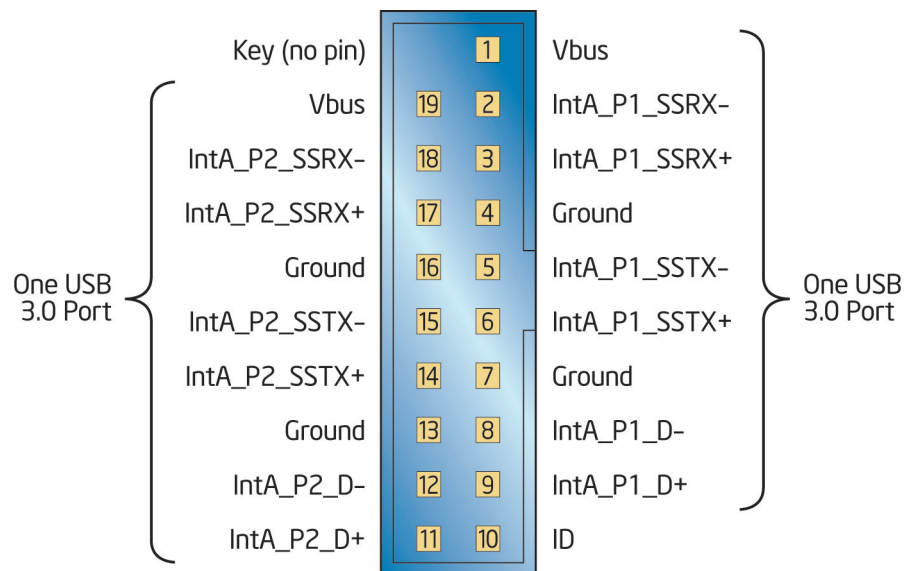
#### NOTE

- The +5 V DC power on the USB connector is fused.
- Use only a front panel USB connector that conforms to the USB 2.0 specification for high-speed USB devices.



OM23948

**Figure 11. Connection Diagram for the Front Panel Dual-Port USB 2.0 Connectors**



OM23934

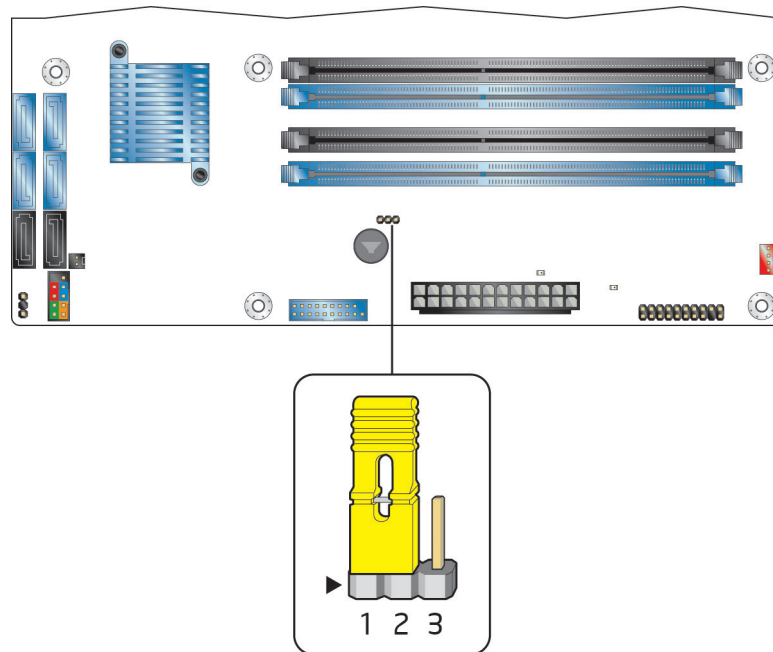
**Figure 12. Connection Diagram for the Front Panel USB 3.0 Connector**

## 2.3 BIOS Security Jumper

**⚠ CAUTION**

*Do not move the jumper with the power on. Always turn off the power and unplug the power cord from the computer before changing a jumper setting. Otherwise, the board could be damaged.*

Figure 13 shows the location of the jumper. The 3-pin jumper determines the BIOS Security program's mode. Table 28 describes the jumper settings for the three modes: normal, lockdown, and configuration.



OM23942

**Figure 13. Location of the Jumper**

**Table 28. BIOS Setup Security Jumper Settings**

Function/Mode	Jumper Setting	Configuration
Normal	1-2	The BIOS uses current configuration information and passwords for booting.
Lockdown	2-3	<p>The BIOS uses current configuration information and passwords for booting, except:</p> <ul style="list-style-type: none"> <li>• All POST Hotkeys are suppressed (prompts are not displayed and keys are not accepted. For example, F2 for Setup, F10 for the Boot Menu).</li> <li>• Power Button Menu is not available (see Section 3.9.3 Power Button Menu).</li> </ul> <p>BIOS updates are not available except for automatic Recovery due to flash corruption.</p>
Configuration Mode	None	<p>BIOS Recovery Update process if a matching *.bio file is found. Recovery Update can be cancelled by pressing the Esc key.</p> <p>If the Recovery Update was cancelled or a matching *.bio file was not found, a Config Menu will be displayed. The Config Menu consists of the following (followed by the Power Button Menu selections):</p> <ul style="list-style-type: none"> <li>[1] Suppress this menu until the BIOS Security Jumper is replaced.</li> <li>[2] Clear BIOS User and Supervisor Passwords.</li> <li>[3] Reset Intel AMT to default factory settings.</li> <li>[4] Clear Trusted Platform Module.</li> </ul> <p>See Section 3.9.3 Power Button Menu.</p>

## 2.4 Mechanical Considerations

### 2.4.1 Form Factor

The board is designed to fit into an ATX-form-factor chassis. Figure 14 illustrates the mechanical form factor for the board. Dimensions are given in inches [millimeters]. The outer dimensions are 9.60 inches by 9.60 inches [243.84 millimeters by 243.84 millimeters]. Location of the I/O connectors and mounting holes are in compliance with the ATX specification.

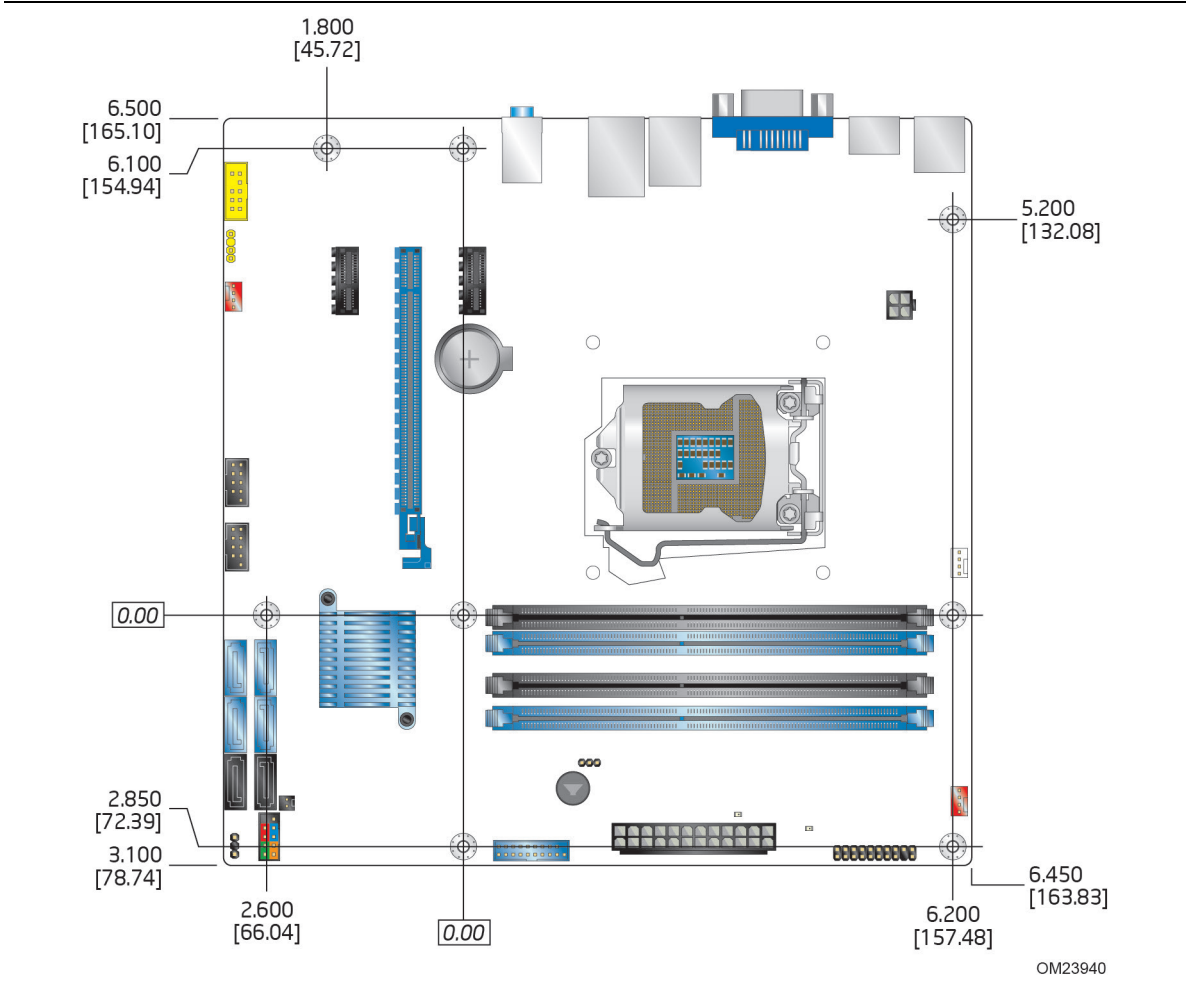


Figure 14. Board Dimensions

## 2.5 Electrical Considerations

### 2.5.1 Power Supply Considerations



#### CAUTION

*The +5 V standby line from the power supply must be capable of providing adequate +5 V standby current. Failure to do so can damage the power supply. The total amount of standby current required depends on the wake devices supported and manufacturing options.*

Additional power required will depend on configurations chosen by the integrator.

Due to improvements in 4<sup>th</sup> generation Intel Core processor power efficiency, the requirements for the processor's power supply have changed. More specifically, the latest Power Supply Design Guide rev 1.3 has indicated a minimum current of 0.05A on +12 V2DC and recommends 0A. This is to prevent Power Supply Unit (PSU) protection from triggering during minimum loading.

Intel recommends that system integrators and builders check the latest list of tested PSUs to find out which are capable of supporting the 4<sup>th</sup> generation Intel Core processor. This list may be found at: <http://www.intel.com/go/powersupplies/>. From the filters at the top right of the page, set **12V2 Min Load 0A** to "Yes" to see which PSUs are capable of supporting the processor's new power requirements.

The power supply must comply with the indicated parameters of the ATX form factor specification.

- The potential relation between 3.3 V DC and +5 V DC power rails
- The current capability of the +5 V<sub>STBY</sub> line
- All timing parameters
- All voltage tolerances

For example, for a high power system consisting of a supported 95 W processor (see Section 1.3 on page 16 for a list of supported processors), 4 GB DDR3 RAM, one high end video card, one hard disk drive, one optical drive, and all board peripherals enabled, the minimum recommended power supply is 460 W.

For example, for a low power system consisting of a supported 45 W processor (see Section 1.3 on page 16 for a list of supported processors), 2 GB DDR3 RAM, integrated graphics, one SSD, one optical drive, and no extra onboard peripherals enabled, the minimum recommended power supply is a 320 W.

#### For information about

#### Refer to

Selecting an appropriate power supply

<http://support.intel.com/support/motherboards/desktop/sb/CS-026472.htm>

Selecting a power supply capable of supporting the 4<sup>th</sup> generation Intel Core processor

<http://www.intel.com/go/powersupplies/>

## 2.5.2 Fan Header Current Capability



### CAUTION

*The processor fan must be connected to the processor fan header, not to a chassis fan header. Connecting the processor fan to a chassis fan header may result in onboard component damage that will halt fan operation.*

Table 29 lists the current capability of the fan headers.

**Table 29. Fan Header Current Capability**

Fan Header	Maximum Available Current
Processor fan	2.0 A
Front chassis fan	1.5 A
Rear chassis fan	1.5 A

## 2.5.3 Add-in Board Considerations

The board is designed to provide 2 A (average) of current for each add-in board from the +5 V rail. The total +5 V current draw for add-in boards for a fully loaded board (all three expansion slots filled) must not exceed the system's power supply +5 V maximum current or 14 A in total.

## 2.6 Thermal Considerations



### CAUTION

*A chassis with a maximum internal ambient temperature of 38 °C at the processor fan inlet is a requirement. Use a processor heat sink that provides omni-directional airflow to maintain required airflow across the processor voltage regulator area.*



### CAUTION

*Failure to ensure appropriate airflow may result in reduced performance of both the processor and/or voltage regulator or, in some instances, damage to the board. For a list of chassis that have been tested with Intel desktop boards please refer to the following website:*

[http://www3.intel.com/cd/channel/reseller/asmo-na/eng/tech\\_reference/53211.htm](http://www3.intel.com/cd/channel/reseller/asmo-na/eng/tech_reference/53211.htm)

*All responsibility for determining the adequacy of any thermal or system design remains solely with the reader. Intel makes no warranties or representations that merely following the instructions presented in this document will result in a system with adequate thermal performance.*



**CAUTION**

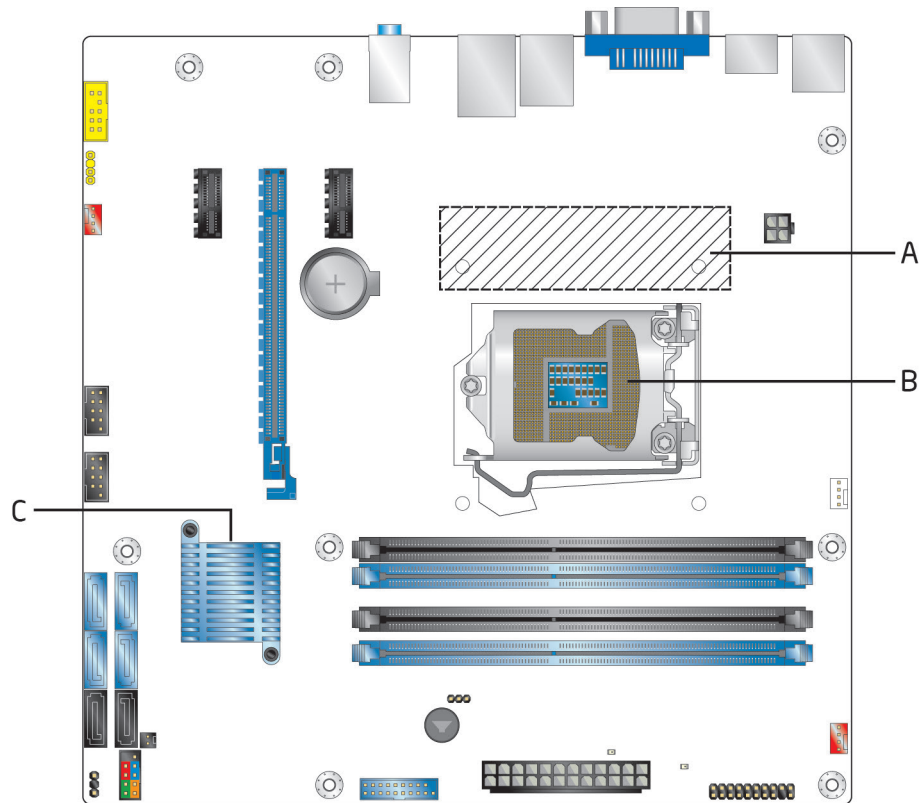
Ensure that the ambient temperature does not exceed the board's maximum operating temperature. Failure to do so could cause components to exceed their maximum case temperature and malfunction. For information about the maximum operating temperature, see the environmental specifications in Section 2.8.



**CAUTION**

Ensure that proper airflow is maintained in the processor voltage regulator circuit. Failure to do so may result in damage to the voltage regulator circuit. The processor voltage regulator area (shown in Figure 15) can reach a temperature of up to 120 °C in an open chassis.

Figure 15 shows the locations of the localized high temperature zones.



OM23941

Item	Description
A	Processor voltage regulator area
B	Processor
C	Intel B85 Express Chipset

**Figure 15. Localized High Temperature Zones**



Table 30 provides maximum case temperatures for the components that are sensitive to thermal changes. The operating temperature, current load, or operating frequency could affect case temperatures. Maximum case temperatures are important when considering proper airflow to cool the board.

**Table 30. Thermal Considerations for Components**

Component	Maximum Case Temperature
Processor	For processor case temperature, see processor datasheets and processor specification updates
Intel B85 Express Chipset	104 °C

To ensure functionality and reliability, the component is specified for proper operation when Case Temperature is maintained at or below the maximum temperature listed in Table 30. This is a requirement for sustained power dissipation equal to Thermal Design Power (TDP is specified as the maximum sustainable power to be dissipated by the components). When the component is dissipating less than TDP, the case temperature should be below the Maximum Case Temperature. The surface temperature at the geometric center of the component corresponds to Case Temperature.

It is important to note that the temperature measurement in the system BIOS is a value reported by embedded thermal sensors in the components and does not directly correspond to the Maximum Case Temperature.

For information about	Refer to
Processor datasheets and specification updates	Section 1.2, page 16
Intel B85 Express Chipset	<a href="http://www.intel.com/products/desktop/chipsets/">http://www.intel.com/products/desktop/chipsets/</a>

## 2.7 Reliability

The Mean Time Between Failures (MTBF) prediction is calculated using a parts count method. The calculation is based on the Telcordia SR-332, Issue 3; Bellcore Method 1 Case 3 with 50% electrical stress, 55 °C component ambient and 25 °C system ambient. The MTBF prediction is used to estimate repair rates and spare parts requirements. The MTBF data is calculated from predicted data at 55 °C. The MTBF for the Intel Desktop Board DB85FL is 377,255 hours.

## 2.8 Environmental

Table 31 lists the environmental specifications for the board.

**Table 31. Environmental Specifications**

Parameter	Specification		
<b>Temperature</b>			
Non-Operating	-20 °C to +70 °C <sup>(Note)</sup>		
Operating	0 °C to +55 °C The operating temperature of the board may be determined by measuring the air temperature from within 1 inch of the edge of the chipset/PCH heatsink and 1 inch above the board, in a closed chassis, while the system is in operation.		
<b>Shock</b>			
Unpackaged	50 g trapezoidal waveform		
	Velocity change of 170 inches/s <sup>2</sup>		
Packaged	Half sine 2 millisecond		
	Product Weight (pounds)	Free Fall (inches)	Velocity Change (inches/s <sup>2</sup> )
	<20	36	167
	21-40	30	152
	41-80	24	136
	81-100	18	118
<b>Vibration</b>			
Unpackaged	5 Hz to 20 Hz: 0.01 g <sup>2</sup> Hz sloping up to 0.02 g <sup>2</sup> Hz		
	20 Hz to 500 Hz: 0.02 g <sup>2</sup> Hz (flat)		
Packaged	5 Hz to 40 Hz: 0.015 g <sup>2</sup> Hz (flat)		
	40 Hz to 500 Hz: 0.015 g <sup>2</sup> Hz sloping down to 0.00015 g <sup>2</sup> Hz		

Note: Before attempting to operate this board, the overall temperature of the board must be above the minimum operating temperature specified. It is recommended that the board temperature be at least room temperature before attempting to power on the board.

# 3 Overview of BIOS Features

## 3.1 Introduction

The board uses an Intel Visual BIOS that is stored in the Serial Peripheral Interface Flash Memory (SPI Flash) and can be updated using a disk-based program. The SPI Flash contains the Visual BIOS Setup program, POST, the PCI auto-configuration utility, LAN EEPROM information, and Plug and Play support.

The BIOS displays a message during POST identifying the type of BIOS and a revision code. The initial production BIOSs are identified as FLB8510H.86A.

When the BIOS Setup configuration jumper is set to configure mode and the computer is powered-up, the BIOS compares the CPU version and the microcode version in the BIOS and reports if the two match.

The BIOS Setup program can be used to view and change the BIOS settings for the computer. The BIOS Setup program is accessed by pressing the <F2> key after the POST memory test begins and before the operating system boot begins.



Figure 16. Intel Visual BIOS Screen

Table 32 lists the BIOS Setup program menu features.

**Table 32. Intel Visual BIOS Setup Display Areas**

Home 1	Home 2	Home 3	Main	Devices & Peripherals	Cooling
Displays processor, graphics, memory, and configuration with quick launch to tuning, UEFI apps, BIOS update, and system profiles	Environmental monitoring display and attached SATA devices	System, desktop board, chassis, and processor information	Displays processor, memory, configuration, event log, date, and time	Configures advanced features available through the chipset and other discrete controllers	Real-time system monitoring, adjust fan speeds, set temperature set points, and define system voltage settings

continued

**Table 32. Intel Visual BIOS Setup Display Areas (continued)**

Performance	Security	Power	Boot	Exit
Displays and Configures Memory, Graphics, Bus, and Processor overrides	Sets passwords and security features	Configures power management features and power supply controls	Selects boot options and boot display options	Saves or discards changes to Setup program options

Table 33 lists the function keys available for menu screens.

**Table 33. BIOS Setup Program Function Keys**

BIOS Setup Program Function Key	Description
<←> or <→>	Selects a different menu screen (Moves the cursor left or right)
<↑> or <↓>	Selects an item (Moves the cursor up or down)
<Tab>	Selects a field (Not implemented)
Mouse	Allows control of all options and slider controls in Intel Visual BIOS
<Enter>	Executes command or selects the submenu
<F9>	Load the default configuration values for the current menu
<F10>	Save the current values and exits the BIOS Setup program
<Esc>	Exits the menu

## 3.2 BIOS Flash Memory Organization

The Serial Peripheral Interface Flash Memory (SPI Flash) includes a 96 Mb (12288 KB) flash memory device.

## 3.3 Resource Configuration

### 3.3.1 PCI Express Autoconfiguration

The BIOS can automatically configure PCI Express devices. PCI Express devices may be onboard or add-in cards. Autoconfiguration lets a user insert or remove PCI Express cards without having to configure the system. When a user turns on the system after adding a PCI Express card, the BIOS automatically configures interrupts, the I/O space, and other system resources. Any interrupts set to Available in Setup are considered to be available for use by the add-in card.

## 3.4 System Management BIOS (SMBIOS)

SMBIOS is a Desktop Management Interface (DMI) compliant method for managing computers in a managed network.

The main component of SMBIOS is the Management Information Format (MIF) database, which contains information about the computing system and its components. Using SMBIOS, a system administrator can obtain the system types, capabilities, operational status, and installation dates for system components. The MIF database defines the data and provides the method for accessing this information. The BIOS enables applications such as third-party management software to use SMBIOS. The BIOS stores and reports the following SMBIOS information:

- BIOS data, such as the BIOS revision level
- Fixed-system data, such as peripherals, serial numbers, and asset tags
- Resource data, such as memory size, cache size, and processor speed
- Dynamic data, such as event detection and error logging

Non-Plug and Play operating systems require an additional interface for obtaining the SMBIOS information. The BIOS supports an SMBIOS table interface for such operating systems. Using this support, an SMBIOS service-level application running on a non-Plug and Play operating system can obtain the SMBIOS information. Additional board information can be found in the BIOS under the Additional Information header under the Main BIOS page.

## 3.5 Legacy USB Support

Legacy USB support enables USB devices to be used even when the operating system's USB drivers are not yet available. Legacy USB support is used to access the BIOS Setup program, and to install an operating system that supports USB. By default, Legacy USB support is set to Enabled.

Legacy USB support operates as follows:

1. When you apply power to the computer, legacy support is disabled.
2. POST begins.
3. Legacy USB support is enabled by the BIOS allowing you to use a USB keyboard to enter and configure the BIOS Setup program and the maintenance menu.
4. POST completes.

5. The operating system loads. While the operating system is loading, USB keyboards and mice are recognized and may be used to configure the operating system. (Keyboards and mice are not recognized during this period if Legacy USB support was set to Disabled in the BIOS Setup program.)
6. After the operating system loads the USB drivers, all legacy and non-legacy USB devices are recognized by the operating system, and Legacy USB support from the BIOS is no longer used.
7. Additional USB legacy feature options can be access by using Intel® Integrator Toolkit version 5.

To install an operating system that supports USB, verify that Legacy USB support in the BIOS Setup program is set to Enabled and follow the operating system's installation instructions.

## 3.6 BIOS Updates

The BIOS can be updated using either of the following utilities, which are available on the Intel World Wide Web site (see Section 1.2 on page 16):

- Intel® Express BIOS Update utility, which enables automated updating while in the Windows environment. Using this utility, the BIOS can be updated from a file on a hard disk, a USB drive (a flash drive or a USB hard drive), or a CD-ROM, or from the file location on the Web.
- Intel® Flash Memory Update Utility, which requires booting from DOS. Using this utility, the BIOS can be updated from a file on a hard disk, a USB drive (a flash drive or a USB hard drive), or a CD-ROM.
- Intel® F7 switch allows a user to select where the BIOS .bio file is located and perform the update from that location/device. Similar to performing a BIOS Recovery without removing the BIOS configuration jumper.
- Intel Visual BIOS Update Utility allows the user to select the BIOS .bio file from the internet, USB device, hard disk drive, or other media.

Both utilities verify that the updated BIOS matches the target system to prevent accidentally installing an incompatible BIOS.



### NOTE

*Review the instructions distributed with the upgrade utility before attempting a BIOS update.*

<b>For information about</b>	<b>Refer to</b>
BIOS update utilities	<a href="http://support.intel.com/support/motherboards/desktop/sb/CS-022312.htm">http://support.intel.com/support/motherboards/desktop/sb/CS-022312.htm</a>

### 3.6.1 Language Support

The BIOS Setup program and help messages are supported in US English.

### 3.6.2 Custom Splash Screen

During POST, an Intel® splash screen is displayed by default. This splash screen can be augmented with a custom splash screen. The Intel Integrator’s Toolkit version 5 that is available from Intel can be used to create a custom splash screen.



**NOTE**

*If you add a custom splash screen, it will share space with the Intel branded logo.*

**For information about**

**Refer to**

Intel Integrator Toolkit

<http://www.intel.com/go/itk>

## 3.7 BIOS Recovery

It is unlikely that anything will interrupt a BIOS update; however, if an interruption occurs, the BIOS could be damaged. Table 34 lists the drives and media types that can and cannot be used for BIOS recovery. The BIOS recovery media does not need to be made bootable.

**Table 34. Acceptable Drives/Media Types for BIOS Recovery**

Media Type	Can be used for BIOS recovery?
CD-ROM drive connected to the SATA interface	Yes
USB removable drive (a USB Flash Drive, for example)	Yes
USB diskette drive (with a 1.44 MB diskette)	No
USB hard disk drive	No

**For information about**

**Refer to**

BIOS recovery

<http://www.intel.com/support/motherboards/desktop/sb/cs-023360.htm>

## 3.8 Boot Options

In the BIOS Setup program, the user can choose to boot from a hard drive, optical drive, removable drive, or the network. The default setting is for the optical drive to be the first boot device, the hard drive second, removable drive third, and the network fourth.

### 3.8.1 Optical Drive Boot

Booting from the optical drive is supported in compliance to the El Torito bootable CD-ROM format specification. Under the Boot menu in the BIOS Setup program, the optical drive is listed as a boot device. Boot devices are defined in priority order. Accordingly, if there is not a bootable CD in the optical drive, the system will attempt to boot from the next defined drive.

### 3.8.2 Network Boot

The network can be selected as a boot device. This selection allows booting from the onboard LAN or a network add-in card with a remote boot ROM installed.

Pressing the <F12> key during POST automatically forces booting from the LAN. To use this key during POST, the User Access Level in the BIOS Setup program's Security menu must be set to Full.

### 3.8.3 Booting Without Attached Devices

For use in embedded applications, the BIOS has been designed so that after passing the POST, the operating system loader is invoked even if the following devices are not present:

- Video adapter
- Keyboard
- Mouse

### 3.8.4 Changing the Default Boot Device During POST

Pressing the <F10> key during POST causes a boot device menu to be displayed. This menu displays the list of available boot devices. Table 35 lists the boot device menu options.

**Table 35. Boot Device Menu Options**

Boot Device Menu Function Keys	Description
<↑> or <↓>	Selects a default boot device
<Enter>	Exits the menu and boots from the selected device
<Esc>	Exits the menu and boots according to the boot priority defined through BIOS setup



## 3.9 Adjusting Boot Speed

These factors affect system boot speed:

- Selecting and configuring peripherals properly
- Optimizing BIOS boot parameters
- Enabling the Fast Boot feature

### 3.9.1 Peripheral Selection and Configuration

The following techniques help improve system boot speed:

- Choose a hard drive with parameters such as “power-up to data ready” in less than eight seconds that minimizes hard drive startup delays.
- Select a CD-ROM drive with a fast initialization rate. This rate can influence POST execution time.
- Eliminate unnecessary add-in adapter features, such as logo displays, screen repaints, or mode changes in POST. These features may add time to the boot process.
- Try different monitors. Some monitors initialize and communicate with the BIOS more quickly, which enables the system to boot more quickly.

### 3.9.2 BIOS Boot Optimizations

Use of the following BIOS Setup program settings reduces the POST execution time:

- In the Boot menu, enable the settings for Fast Boot. This option will allow the BIOS to skip through various stages of POST and boot quickly to the last detected boot device.
- In the Boot Menu, set the hard disk drive as the first boot device. As a result, the POST does not first seek a diskette drive, which saves about one second from the POST execution time.
- In the Peripheral Configuration submenu, disable the LAN device if it will not be used. This can reduce option ROM boot time by up to four seconds.



#### **NOTE**

*It is possible to optimize the boot process to the point where the system boots so quickly that the Intel logo screen (or a custom logo splash screen) will not be seen. Monitors and hard disk drives with minimum initialization times can also contribute to a boot time that might be so fast that necessary logo screens and POST messages cannot be seen.*

*This boot time may be so fast that some drives might be not be initialized at all. If this condition should occur, it is possible to introduce a programmable delay ranging from zero to 30 seconds by 5 second increments (using the Hard Disk Pre-Delay feature of the Advanced Menu in the Drive Configuration Submenu of the BIOS Setup program).*

### 3.9.3 Power Button Menu

The Power Button Menu can be accessed during power on if the user presses the power button and holds it down until three short beep sounds are emitted by the board piezoelectric speaker. The BIOS will display the following prompt and wait for a keystroke:

- [ESC] Normal Boot
- [F2] Intel Visual BIOS
- [F3] Disable Fast Boot
- [F4] BIOS Recovery
- [F7] Update BIOS
- [F10] Enter Boot Menu
- [F12] Network Boot

If an unrecognized key is pressed, the BIOS will beep and wait for another keystroke. If one of the listed hotkeys is pressed, the BIOS will follow the indicated boot path. Password requirements must still be honored.

If Disable Fast Boot is selected, the BIOS will disable all Fast Boot optimizations and reset the system.

## 3.10 Hard Disk Drive Password Security Feature

The Hard Disk Drive Password Security feature blocks read and write accesses to the hard disk drive until the correct password is given. Hard Disk Drive Passwords are set in BIOS SETUP and are prompted for during BIOS POST. For convenient support of S3 resume, the system BIOS will automatically unlock drives on resume from S3. Valid password characters are A-Z, a-z, and 0-9. Passwords may be up to 16 characters in length.

The User hard disk drive password, when installed, will be required upon each power-cycle until the Master Key or User hard disk drive password is submitted.

The Master Key hard disk drive password, when installed, will not lock the drive. The Master Key hard disk drive password exists as an unlock override in the event that the User hard disk drive password is forgotten. Only the installation of the User hard disk drive password will cause a hard disk to be locked upon a system power-cycle.

Table 36 shows the effects of setting the Hard Disk Drive Passwords.

**Table 36. Master Key and User Hard Drive Password Functions**

Password Set	Password During Boot
Neither	None
Master only	None
User only	User only
Master and User Set	Master or User

During every POST, if a User hard disk drive password is set, POST execution will pause with the following prompt to force the user to enter the Master Key or User hard disk drive password:

```
Enter Hard Disk Drive Password:
```

Upon successful entry of the Master Key or User hard disk drive password, the system will continue with normal POST.

If the hard disk drive password is not correctly entered, the system will go back to the above prompt. The user will have three attempts to correctly enter the hard disk drive password. After the third unsuccessful hard disk drive password attempt, the system will halt with the message:

```
Hard Disk Drive Password Entry Error
```

A manual power cycle will be required to resume system operation.



## NOTE

*As implemented on DB85FL, Hard Disk Drive Password Security is only supported on SATA port 0. The passwords are stored on the hard disk drive so if the drive is relocated to another SATA port or computer that does not support Hard Disk Drive Password Security feature, the drive will not be accessible.*



## NOTE

*Hard Disk Drive Password Security is not supported in PCH RAID mode. Secured hard disk drives attached to the system when the system is in PCH RAID mode will not be accessible due to the disabling of BIOS Hard Disk Drive Password support.*

## 3.11 BIOS Security Features

The BIOS includes security features that restrict access to the BIOS Setup program and who can boot the computer. A supervisor password and a user password can be set for the BIOS Setup program and for booting the computer, with the following restrictions:

- The supervisor password gives unrestricted access to view and change all the Setup options in the BIOS Setup program. This is the supervisor mode.
- The user password gives restricted access to view and change Setup options in the BIOS Setup program. This is the user mode.
- If only the supervisor password is set, pressing the <Enter> key at the password prompt of the BIOS Setup program allows the user restricted access to Setup.
- If both the supervisor and user passwords are set, users can enter either the supervisor password or the user password to access Setup. Users have access to Setup respective to which password is entered.
- Setting the user password restricts who can boot the computer. The password prompt will be displayed before the computer is booted. If only the supervisor password is set, the computer boots without asking for a password. If both passwords are set, the user can enter either password to boot the computer.

- For enhanced security, use different passwords for the supervisor and user passwords.
- Valid password characters are A-Z, a-z, and 0-9. Passwords may be up to 19 characters in length.

Table 37 shows the effects of setting the supervisor password and user password. This table is for reference only and is not displayed on the screen.

**Table 37. Supervisor and User Password Functions**

Password Set	Supervisor Mode	User Mode	Setup Options	Password to Enter Setup	Password During Boot
Neither	Can change all options (Note)	Can change all options (Note)	None	None	None
Supervisor only	Can change all options	Can change a limited number of options	Supervisor Password	Supervisor	None
User only	N/A	Can change all options	Enter Password Clear User Password	User	User
Supervisor and user set	Can change all options	Can change a limited number of options	Supervisor Password Enter Password	Supervisor or user	Supervisor or user

Note: If no password is set, any user can change all Setup options.



**NOTE**

The BIOS complies with NIST Special Publication 800-147 BIOS Protection Guidelines / Recommendations of the National Institute of Standards and Technology. Refer to <http://csrc.nist.gov/publications/nistpubs/800-147/NIST-SP800-147-April2011.pdf> for more information.

### 3.12 BIOS Performance Features

The BIOS includes the following options to provide custom performance enhancements when using 4<sup>th</sup> generation Intel Core processors in an LGA1150 socket.

- Processor maximum non-turbo ratio (processor multiplier can only be adjusted down)
- Memory multiplier adjustment
- Memory voltage adjustment
- Memory latency adjustments
- Graphics multiplier adjustment
- Graphics voltage adjustment

# 4 BIOS Error Codes and Messages

---

## 4.1 BIOS Error Codes

The BIOS provides two types of Error Code indications during POST:

- Beep codes
- Blink codes

### 4.1.1 BIOS Beep Codes

Whenever a recoverable error occurs during POST, the BIOS causes the board's speaker (Figure 1, S) to beep an error code describing the problem (see Table 38).

**Table 38. BIOS Beep Codes**

Type	Pattern	Frequency
F2 Setup/F10 Boot Menu Prompt	One 0.5 second beep when BIOS is ready to accept keyboard input.	932 Hz
BIOS update in progress	None	
Video error	On-off (1.0 second each) two times, then 2.5-second pause (off), entire pattern repeats (beeps and pause) once and the BIOS will continue to boot.	932 Hz When no VGA option ROM is found.
Memory error	On-off (1.0 second each) three times, then 2.5-second pause (off), entire pattern repeats (beeps and pause) until the system is powered off.	932 Hz
Thermal trip warning	Alternate high and low beeps (1.0 second each) for eight beeps, followed by system shut down.	High beep 2000 Hz Low beep 1500 Hz

## 4.1.2 Front-panel Power LED Blink Codes

Whenever a recoverable error occurs during POST, the BIOS causes the board's front panel power LED to blink an error code describing the problem (see Table 39).

**Table 39. Front-panel Power LED Blink Codes**

Type	Pattern	Note
F2 Setup/F10 Boot Menu Prompt	None	
BIOS update in progress	Off when the update begins, then on for 0.5 seconds, then off for 0.5 seconds. The pattern repeats until the BIOS update is complete.	
Video error	On-off (1.0 second each) two times, then 2.5-second pause (off), entire pattern repeats (blink and pause) until the system is powered off.	When no VGA option ROM is found.
Memory error	On-off (1.0 second each) three times, then 2.5-second pause (off), entire pattern repeats (blinks and pause) until the system is powered off.	
Thermal trip warning	Each beep will be accompanied by the following blink pattern: .25 seconds on, .25 seconds off, .25 seconds on, .25 seconds off. This will result in a total of 16 blinks.	

## 4.2 BIOS Error Messages

The BIOS also displays error messages during POST. Table 40 lists the error messages and provides a brief description of each.

**Table 40. BIOS Error Messages**

Error Message	Explanation
CMOS Battery Low	The battery may be losing power. Replace the battery soon.
CMOS Checksum Bad	The CMOS checksum is incorrect. CMOS memory may have been corrupted. Run Setup to reset values.
Memory Size Decreased	Memory size has decreased since the last boot. If no memory was removed, then memory may be bad.
No Boot Device Available	System did not find a device to boot.

# 5 Regulatory Compliance and Battery Disposal Information

---

## 5.1 Regulatory Compliance

This section contains the following regulatory compliance information for Intel Desktop Board DB85FL:

- Safety standards
- European Union Declaration of Conformity statement
- Product Ecology statements
- Electromagnetic Compatibility (EMC) standards
- Product certification markings

### 5.1.1 Safety Standards

Intel Desktop Board DB85FL complies with the safety standards stated in Table 41 when correctly installed in a compatible host system.

**Table 41. Safety Standards**

<b>Standard</b>	<b>Title</b>
CSA/UL 60950-1	Information Technology Equipment – Safety - Part 1: General Requirements (USA and Canada)
EN 60950-1	Information Technology Equipment – Safety - Part 1: General Requirements (European Union)
IEC 60950-1	Information Technology Equipment – Safety - Part 1: General Requirements (International)

## 5.1.2 European Union Declaration of Conformity Statement

We, Intel Corporation, declare under our sole responsibility that the product Intel® Desktop Board DB85FL is in conformity with all applicable essential requirements necessary for CE marking, following the provisions of the European Council Directive 2004/108/EC (EMC Directive), 2006/95/EC (Low Voltage Directive), and 2002/95/EC (ROHS Directive).

The product is properly CE marked demonstrating this conformity and is for distribution within all member states of the EU with no restrictions.



This product follows the provisions of the European Directives 2004/108/EC, 2006/95/EC, and 2002/95/EC.

**Čeština** Tento výrobek odpovídá požadavkům evropských směrnic 2004/108/EC, 2006/95/EC a 2002/95/EC.

**Dansk** Dette produkt er i overensstemmelse med det europæiske direktiv 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Dutch** Dit product is in navolging van de bepalingen van Europees Directief 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Eesti** Antud toode vastab Euroopa direktiivides 2004/108/EC, ja 2006/95/EC ja 2002/95/EC kehtestatud nõuetele.

**Suomi** Tämä tuote noudattaa EU-direktiivin 2004/108/EC, 2006/95/EC & 2002/95/EC määräyksiä.

**Français** Ce produit est conforme aux exigences de la Directive Européenne 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Deutsch** Dieses Produkt entspricht den Bestimmungen der Europäischen Richtlinie 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Ελληνικά** Το παρόν προϊόν ακολουθεί τις διατάξεις των Ευρωπαϊκών Οδηγιών 2004/108/EC, 2006/95/EC και 2002/95/EC.

**Magyar** E termék megfelel a 2004/108/EC, 2006/95/EC és 2002/95/EC Európai Irányelv előírásainak.

**Icelandic** Þessi vara stenst reglugerð Evrópska Efnahags Bandalagsins númer 2004/108/EC, 2006/95/EC, & 2002/95/EC.

**Italiano** Questo prodotto è conforme alla Direttiva Europea 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Latviešu** Šis produkts atbilst Eiropas Direktīvu 2004/108/EC, 2006/95/EC un 2002/95/EC noteikumiem.

**Lietuvių** Šis produktas atitinka Europos direktyvų 2004/108/EC, 2006/95/EC, ir 2002/95/EC nuostatas.

**Malti** Dan il-prodott hu konformi mal-provvedimenti tad-Direttivi Ewropej 2004/108/EC, 2006/95/EC u 2002/95/EC.

**Norsk** Dette produktet er i henhold til bestemmelsene i det europeiske direktivet 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Polski** Niniejszy produkt jest zgodny z postanowieniami Dyrektyw Unii Europejskiej 2004/108/EC, 206/95/EC i 2002/95/EC.



**Portuguese** Este produto cumpre com as normas da Diretiva Europeia 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Español** Este producto cumple con las normas del Directivo Europeo 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Slovensky** Tento produkt je v súlade s ustanoveniami európskych direktív 2004/108/EC, 2006/95/EC a 2002/95/EC.

**Slovenščina** Izdelek je skladen z določbami evropskih direktiv 2004/108/EC, 2006/95/EC in 2002/95/EC.

**Svenska** Denna produkt har tillverkats i enlighet med EG-direktiv 2004/108/EC, 2006/95/EC & 2002/95/EC.

**Türkçe** Bu ürün, Avrupa Birliği'nin 2004/108/EC, 2006/95/EC ve 2002/95/EC yönergelerine uyar.

### **5.1.3 Product Ecology Statements**

The following information is provided to address worldwide product ecology concerns and regulations.

#### **5.1.3.1 Disposal Considerations**

This product contains the following materials that may be regulated upon disposal: printed wiring board assembly and lithium battery.

### 5.1.4 China RoHS

Intel Desktop Board DB85FL is a China RoHS-compliant product.

The China Ministry of Information Industry (MII) stipulates that a material Self Declaration Table (SDT) must be included in a product’s user documentation. The SDT for Intel Desktop Board DB85FL is shown in Figure 17.

关于符合中国《电子信息产品污染控制管理办法》的声明

**Management Methods on Control of Pollution from  
Electronic Information Products  
(China RoHS declaration)**

产品中有毒有害物质的名称及含量

部件名称 (Parts)	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
主板组件 Motherboard Assembly	×	○	○	○	○	○
<p>○：表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T 11363-2006 标准规定的限量要求以下。</p> <p>○：Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006.</p> <p>×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准规定的限量要求。</p> <p>×：Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.</p> <p>对销售之日的所售产品,本表显示我公司供应链的电子信息产品可能包含这些物质。注意：在所售产品中可能会也可能不会含有所有所列的部件。</p> <p>This table shows where these substances may be found in the supply chain of our electronic information products, as of the date of sale of the enclosed product. Note that some of the component types listed above may or may not be a part of the enclosed product.</p>						

**Figure 17. Intel Desktop Board DB85FL China RoHS Material Self Declaration Table**

### 5.1.5 EMC Regulations

Intel Desktop Board DB85FL complies with the EMC regulations stated in Table 42 when correctly installed in a compatible host system.

**Table 42. EMC Regulations**

Regulation	Title
FCC 47 CFR Part 15, Subpart B	Title 47 of the Code of Federal Regulations, Part 15, Subpart B, Radio Frequency Devices. (USA)
ICES-003	Interference-Causing Equipment Standard, Digital Apparatus. (Canada)
EN55022	Limits and methods of measurement of Radio Interference Characteristics of Information Technology Equipment. (European Union)
EN55024	Information Technology Equipment – Immunity Characteristics Limits and methods of measurement. (European Union)
EN55022	Australian Communications Authority, Standard for Electromagnetic Compatibility. (Australia and New Zealand)
CISPR 22	Limits and methods of measurement of Radio Disturbance Characteristics of Information Technology Equipment. (International)
CISPR 24	Information Technology Equipment – Immunity Characteristics – Limits and Methods of Measurement. (International)
VCCI V-3, V-4	Voluntary Control for Interference by Information Technology Equipment. (Japan)
KN-22, KN-24	Korean Communications Commission – Framework Act on Telecommunications and Radio Waves Act (South Korea)
CNS 13438	Bureau of Standards, Metrology, and Inspection (Taiwan)

#### FCC Declaration of Conformity

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

For questions related to the EMC performance of this product, contact:

Intel Corporation, 5200 N.E. Elam Young Parkway, Hillsboro, OR 97124  
1-800-628-8686

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and the receiver.

- Connect the equipment to an outlet on a circuit other than the one to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Any changes or modifications to the equipment not expressly approved by Intel Corporation could void the user's authority to operate the equipment.

Tested to comply with FCC standards for home or office use.

**Canadian Department of Communications Compliance Statement**

This digital apparatus does not exceed the Class B limits for radio noise emissions from digital apparatus set out in the Radio Interference Regulations of the Canadian Department of Communications.

Le présent appareil numérique n'émet pas de bruits radioélectriques dépassant les limites applicables aux appareils numériques de la classe B prescrites dans le Règlement sur le brouillage radioélectrique édicté par le ministère des Communications du Canada.

**Japan VCCI Statement**

Japan VCCI Statement translation: This is a Class B product based on the standard of the Voluntary Control Council for Interference from Information Technology Equipment (VCCI). If this is used near a radio or television receiver in a domestic environment, it may cause radio interference. Install and use the equipment according to the instruction manual.

この装置は、情報処理装置等電波障害自主規制協議会（VCCI）の基準に基づくクラスB情報技術装置です。この装置は、家庭環境で使用することを目的としていますが、この装置がラジオやテレビジョン受信機に近接して使用されると、受信障害を引き起こすことがあります。  
取扱説明書に従って正しい取り扱いをして下さい。

**Korea Class B Statement**

Korea Class B Statement translation: This equipment is for home use, and has acquired electromagnetic conformity registration, so it can be used not only in residential areas, but also other areas.

이 기기는 가정용(B급)으로 전자파적합등록을 한 기기로서 주로 가정에서 사용하는 것을 목적으로 하며, 모든 지역에서 사용할 수 있습니다.

## 5.1.6 e-Standby and ErP Compliance

Intel Desktop Board DB85FL allows for a compliant system built to meet the following program requirements, including appropriate selection of an efficient power supply:









- EPEAT\*
- Korea e-Standby
- European Union Energy-related Products Directive (ErP) Lot 6, Tier 2

<b>For information about</b>	<b>Refer to</b>
Electronic Product Environmental Assessment Tool (EPEAT)	<a href="http://www.epeat.net/">http://www.epeat.net/</a>
Korea e-Standby Program	<a href="http://www.kemco.or.kr/new_eng/pg02/pg02100300.asp">http://www.kemco.or.kr/new_eng/pg02/pg02100300.asp</a>
European Union Energy-related Products Directive 2009 (ErP)	<a href="http://ec.europa.eu/enterprise/policies/sustainable-business/sustainable-product-policy/ecodesign/index_en.htm">http://ec.europa.eu/enterprise/policies/sustainable-business/sustainable-product-policy/ecodesign/index_en.htm</a>

### 5.1.7 Regulatory Compliance Marks (Board Level)

Intel Desktop Board DB85FL has the regulatory compliance marks shown in Table 43.

**Table 43. Regulatory Compliance Marks**

Description	Mark
UL joint US/Canada Recognized Component mark. Includes adjacent UL file number for Intel Desktop Boards: E210882.	
FCC Declaration of Conformity logo mark for Class B equipment.	
CE mark. Declaring compliance to the European Union (EU) EMC directive, Low Voltage directive, and RoHS directive.	
Australian Communications Authority (ACA) and New Zealand Radio Spectrum Management (NZ RSM) C-tick mark. Includes adjacent Intel supplier code number, N-232.	
Japan VCCI (Voluntary Control Council for Interference) mark.	
Korea Certification mark. Includes an adjacent KCC (Korean Communications Commission) certification number: KCC-REM-CPU-DB85FL.	
Taiwan BSMI (Bureau of Standards, Metrology and Inspections) mark. Includes adjacent Intel company number, D33025.	
Printed wiring board manufacturer's recognition mark. Consists of a unique UL recognized manufacturer's logo, along with a flammability rating (solder side).	V-0
China RoHS/Environmentally Friendly Use Period Logo: This is an example of the symbol used on Intel Desktop Boards and associated collateral. The color of the mark may vary depending upon the application. The Environmental Friendly Usage Period (EFUP) for Intel Desktop Boards has been determined to be 10 years.	

## 5.2 Battery Disposal Information



### **CAUTION**

*Risk of explosion if the battery is replaced with an incorrect type. Batteries should be recycled where possible. Disposal of used batteries must be in accordance with local environmental regulations.*



### **PRÉCAUTION**

*Risque d'explosion si la pile usagée est remplacée par une pile de type incorrect. Les piles usagées doivent être recyclées dans la mesure du possible. La mise au rebut des piles usagées doit respecter les réglementations locales en vigueur en matière de protection de l'environnement.*



### **FORHOLDSREGEL**

*Eksplosionsfare, hvis batteriet erstattes med et batteri af en forkert type. Batterier bør om muligt genbruges. Bortskaffelse af brugte batterier bør foregå i overensstemmelse med gældende miljølovgivning.*



### **OBS!**

*Det kan oppstå eksplosjonsfare hvis batteriet skiftes ut med feil type. Brukte batterier bør kastes i henhold til gjeldende miljølovgivning.*



### **VIKTIGT!**

*Risk för explosion om batteriet ersätts med felaktig batterityp. Batterier ska kasseras enligt de lokala miljövårdsbestämmelserna.*



### **VARO**

*Räjähdyksvaara, jos pariston tyyppi on väärä. Paristot on kierrätettävä, jos se on mahdollista. Käytetyt paristot on hävitettävä paikallisten ympäristömääräysten mukaisesti.*



### **VORSICHT**

*Bei falschem Einsetzen einer neuen Batterie besteht Explosionsgefahr. Die Batterie darf nur durch denselben oder einen entsprechenden, vom Hersteller empfohlenen Batterietyp ersetzt werden. Entsorgen Sie verbrauchte Batterien den Anweisungen des Herstellers entsprechend.*



### **AVVERTIMENTO**

*Esiste il pericolo di un esplosione se la pila non viene sostituita in modo corretto. Utilizzare solo pile uguali o di tipo equivalente a quelle consigliate dal produttore. Per disfarsi delle pile usate, seguire le istruzioni del produttore.*



### PRECAUCIÓN

*Existe peligro de explosión si la pila no se cambia de forma adecuada. Utilice solamente pilas iguales o del mismo tipo que las recomendadas por el fabricante del equipo. Para deshacerse de las pilas usadas, siga igualmente las instrucciones del fabricante.*



### WAARSCHUWING

*Er bestaat ontploffingsgevaar als de batterij wordt vervangen door een onjuist type batterij. Batterijen moeten zoveel mogelijk worden gerecycled. Houd u bij het weggooien van gebruikte batterijen aan de plaatselijke milieuwetgeving.*



### ATENÇÃO

*Haverá risco de explosão se a bateria for substituída por um tipo de bateria incorreto. As baterias devem ser recicladas nos locais apropriados. A eliminação de baterias usadas deve ser feita de acordo com as regulamentações ambientais da região.*



### AŚCIAROŻZNAŚĆ

*Існуе рызыка выбуху, калі заменены акумулятар неправільнага тыпу. Акумулятары павінны, па магчымасці, перепрацоўвацца. Пазбаўляцца ад старых акумулятараў патрэбна згодна з мясцовымі заканадаўствам па экалогіі.*



### UPOZORNĚNÍ

*V případě výměny baterie za nesprávný druh může dojít k výbuchu. Je-li to možné, baterie by měly být recyklovány. Baterie je třeba zlikvidovat v souladu s místními předpisy o životním prostředí.*



### Προσοχή

*Υπάρχει κίνδυνος για έκρηξη σε περίπτωση που η μπαταρία αντικατασταθεί από μία λανθασμένου τύπου. Οι μπαταρίες θα πρέπει να ανακυκλώνονται όταν κάτι τέτοιο είναι δυνατό. Η απόρριψη των χρησιμοποιημένων μπαταριών πρέπει να γίνεται σύμφωνα με τους κατά τόπο περιβαλλοντικούς κανονισμούς.*



### VIGYÁZAT

*Ha a telepet nem a megfelelő típusú telepre cseréli, az felrobbanhat. A telepeket lehetőség szerint újra kell hasznosítani. A használt telepeket a helyi környezetvédelmi előírásoknak megfelelően kell kiselejtezni.*



### 注意

異なる種類の電池を使用すると、爆発の危険があります。リサイクルが可能な地域であれば、電池をリサイクルしてください。使用後の電池を破棄する際には、地域の環境規制に従ってください。





### **AWAS**

*Risiko letupan wujud jika bateri digantikan dengan jenis yang tidak betul. Bateri sepatutnya dikitar semula jika boleh. Pelupusan bateri terpakai mestilah mematuhi peraturan alam sekitar tempatan.*



### **OSTRZEŻENIE**

*Istnieje niebezpieczeństwo wybuchu w przypadku zastosowania niewłaściwego typu baterii. Zużyte baterie należy w miarę możliwości utylizować zgodnie z odpowiednimi przepisami ochrony środowiska.*



### **PRECAUȚIE**

*Risc de explozie, dacă bateria este înlocuită cu un tip de baterie necorespunzător. Bateriile trebuie reciclate, dacă este posibil. Depozitarea bateriilor uzate trebuie să respecte reglementările locale privind protecția mediului.*



### **ВНИМАНИЕ**

*При использовании батареи несоответствующего типа существует риск ее взрыва. Батареи должны быть утилизированы по возможности. Утилизация батарей должна проводиться по правилам, соответствующим местным требованиям.*



### **UPOZORNENIE**

*Ak batériu vymeníte za nesprávny typ, hrozí nebezpečenstvo jej výbuchu. Batérie by sa mali podľa možnosti vždy recyklovať. Likvidácia použitých batérií sa musí vykonávať v súlade s miestnymi predpismi na ochranu životného prostredia.*



### **POZOR**

*Zamenjava baterije z baterijo drugačnega tipa lahko povzroči eksplozijo. Če je mogoče, baterije reciklirajte. Rabljene baterije zavržite v skladu z lokalnimi okoljevarstvenimi predpisi.*



### **คำเตือน**

*ระวังการระเบิดที่เกิดจากเปลี่ยนแบตเตอรี่ผิดประเภท หากเป็นไปได้ ควรนำแบตเตอรี่ไปรีไซเคิล การทิ้งแบตเตอรี่แล้วต้องเป็นไปตามกฎข้อบังคับด้านสิ่งแวดล้อมของท้องถิ่น.*



### **UYARI**

*Yanlış türde pil takıldığında patlama riski vardır. Piller mümkün olduğunda geri dönüştürülmelidir. Kullanılmış piller, yerel çevre yasalarına uygun olarak atılmalıdır.*



### **ОСТОРОГА**

*Використовуйте батареї правильного типу, інакше існуватиме ризик вибуху. Якщо можливо, використані батареї слід утилізувати. Утилізація використаних батарей має бути виконана згідно місцевих норм, що регулюють охорону довкілля.*



### 小心

如果更換的電池類型不正確，可能會有爆炸的危險。請盡可能將電池送至回收處。請依照當地的環保規範來處理使用過的電池。



### 주의

배터리를 잘못된 종류로 교체할 경우 폭발 위험이 있습니다. 가능한 경우 배터리는 재활용해야 하며, 수명이 다한 배터리를 폐기할 때는 각 지역의 환경법을 따라야 합니다.



### THẬN TRỌNG

*Có nguy cơ xảy ra nổ nếu thay pin không đúng loại. Pin cần được tái chế nếu có thể thực hiện được. Việc thải bỏ pin đã sử dụng phải tuân theo các quy định của địa phương về môi trường.*



### UPOZORNĚNÍ

*V případě výměny baterie za nesprávný druh může dojít k výbuchu. Je-li to možné, baterie by měly být recyklovány. Baterie je třeba zlikvidovat v souladu s místními předpisy o životním prostředí.*



### ETTEVAATUST

*Kui patarei asendatakse uue ebasobivat tüüpi patareiga, võib tekkida plahvatusoht. Tühjad patareid tuleb võimaluse korral viia vastavasse kogumispunkti. Tühjade patareide äraviskamisel tuleb järgida kohalikke keskkonnakaitse alaseid reegleid.*



### FIGYELMEZTETÉS

*Ha az elemet nem a megfelelő típusúra cseréli, felrobbanhat. Az elemeket lehetőség szerint újra kell hasznosítani. A használt elemeket a helyi környezetvédelmi előírásoknak megfelelően kell kiselejtezni.*



### UZMANĪBU

*Pastāv eksplozijas risks, ja baterijas tiek nomainītas ar nepareiza veida baterijām. Ja iespējams, baterijas vajadzētu nodot attiecīgos pieņemšanas punktus. Bateriju izmešanai atkritumos jānotiek saskaņā ar vietējiem vides aizsardzības noteikumiem.*



### DĒMESIO

*Naudojant netinkamo tipo baterijas įrenginys gali sprogti. Kai tik įmanoma, baterijas reikia naudoti pakartotinai. Panaudotas baterijas išmesti būtina pagal vietinius aplinkos apsaugos nuostatus.*



### ATTENZJONI

*Riskju ta' splużjoni jekk il-batterija tinbidel b'tip ta' batterija mhux korrett. Il-batteriji għandhom jiġu riċiklati fejn hu possibbli. Ir-rimi ta' batteriji użati għandu jsir skond ir-regolamenti ambjentali lokali.*



### OSTRZEŻENIE

*Ryzyko wybuchu w przypadku wymiany na baterie niewłaściwego typu. W miarę możliwości baterie należy poddać recyklingowi. Zużytych baterii należy pozbywać się zgodnie z lokalnie obowiązującymi przepisami w zakresie ochrony środowiska.*

